

FIG.1

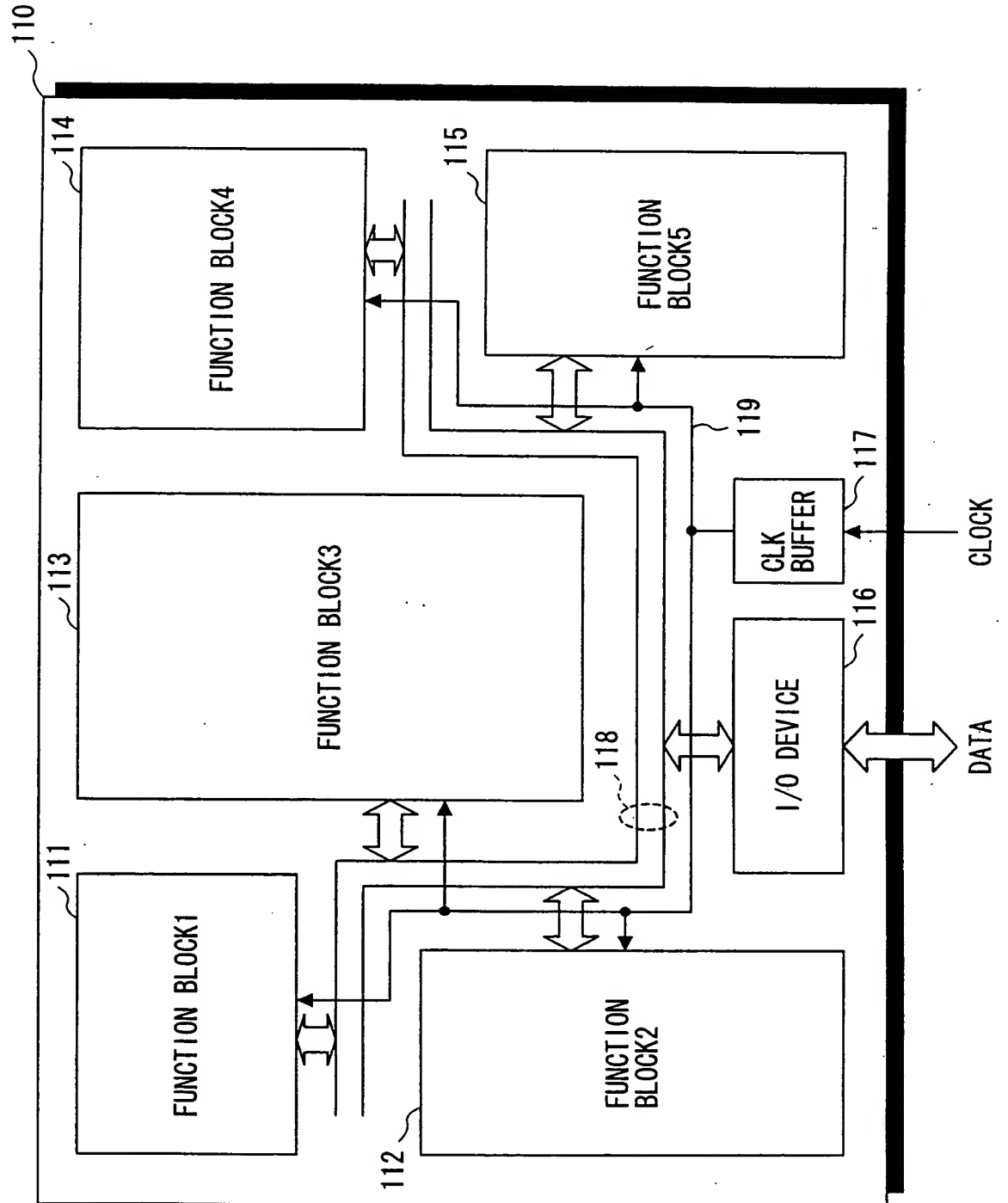


FIG.2

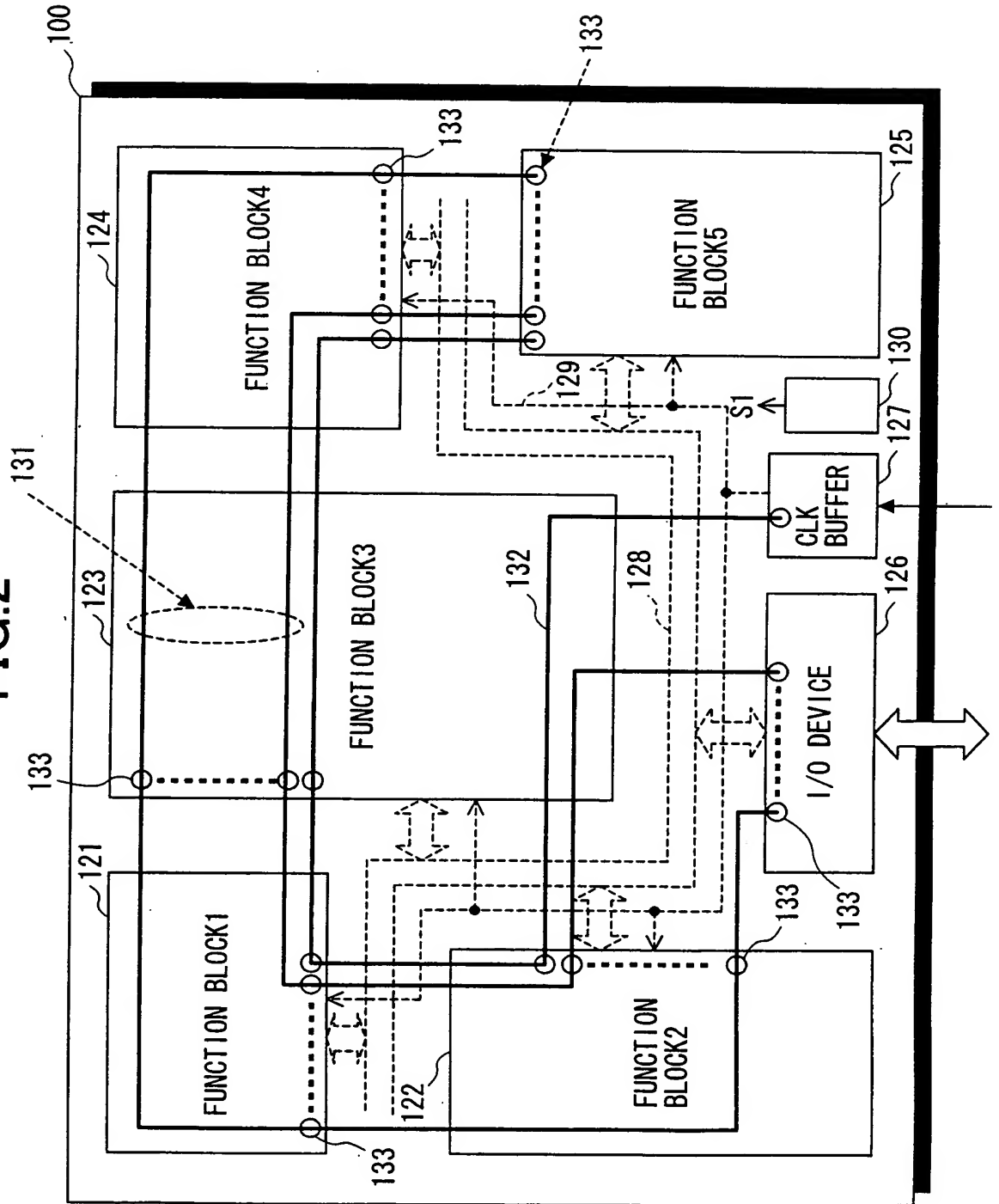


FIG. 3

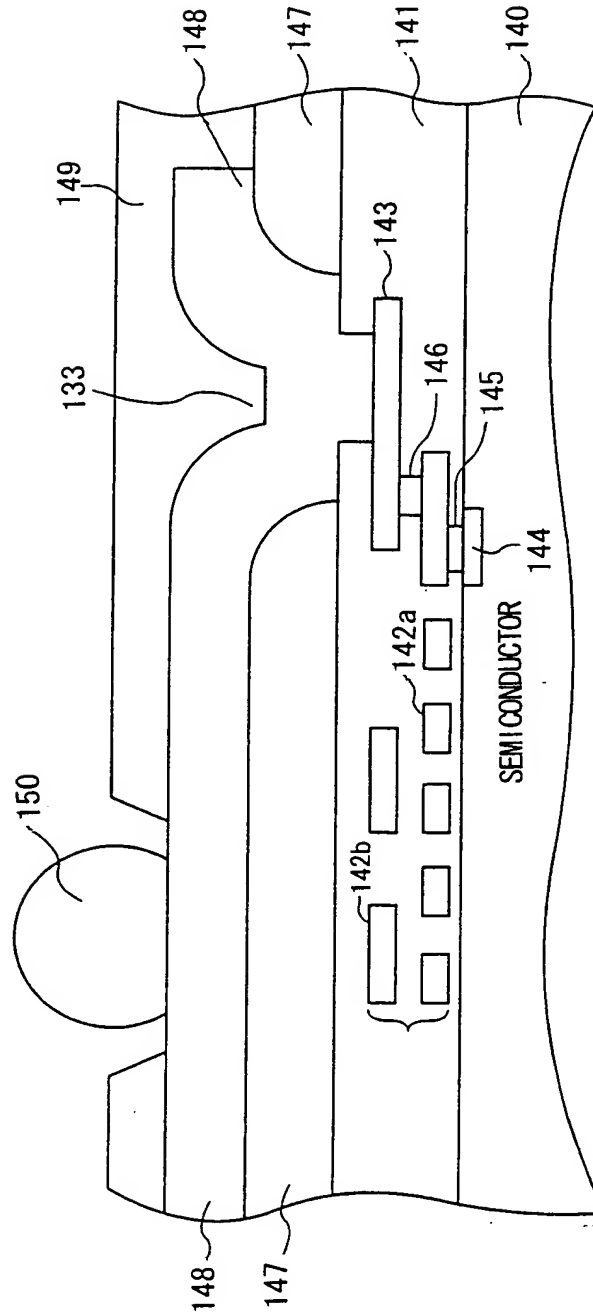
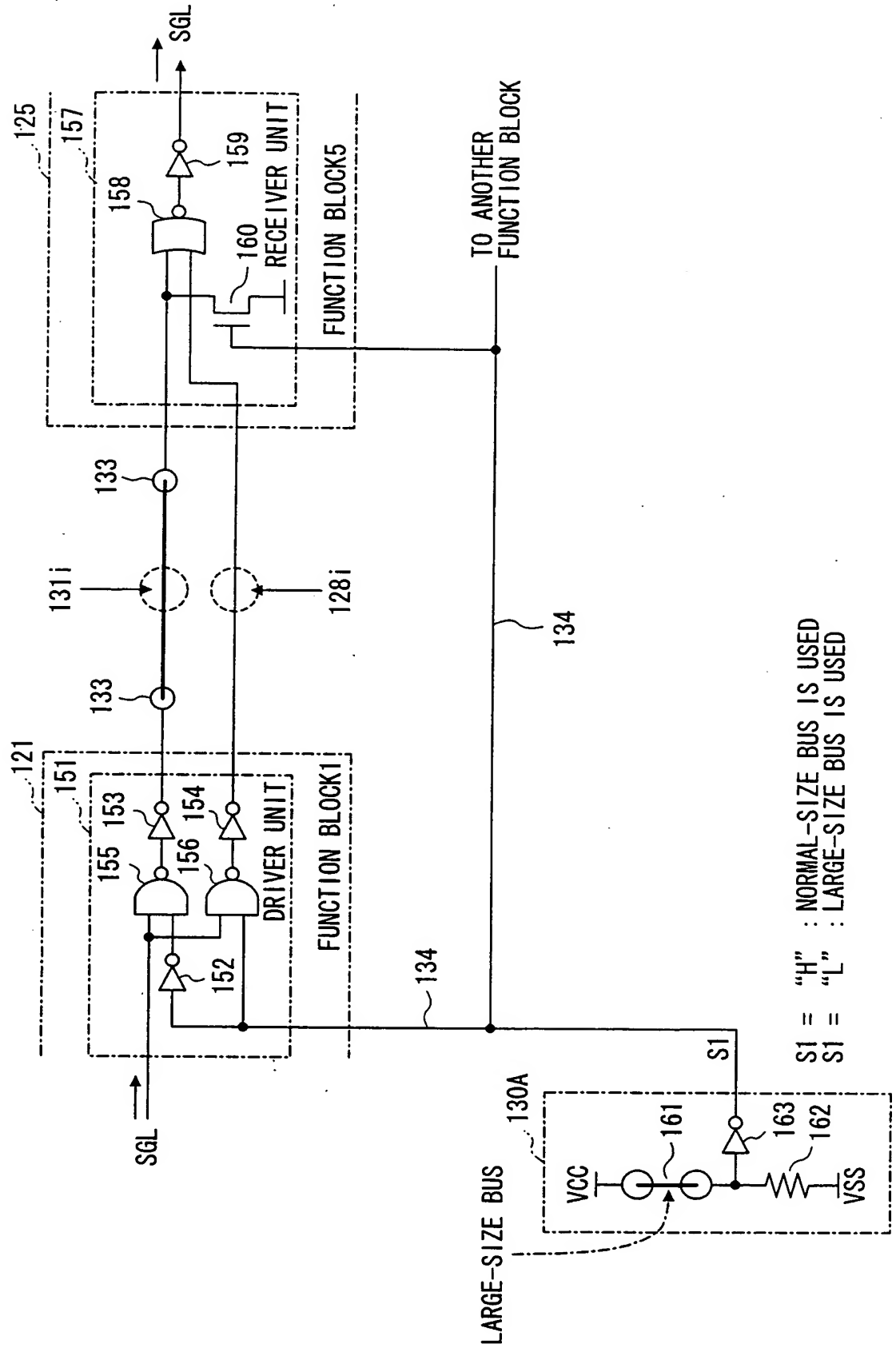


FIG.4



S1 = "H" : NORMAL-SIZE BUS IS USED  
S1 = "L" : LARGE-SIZE BUS IS USED

FIG.5

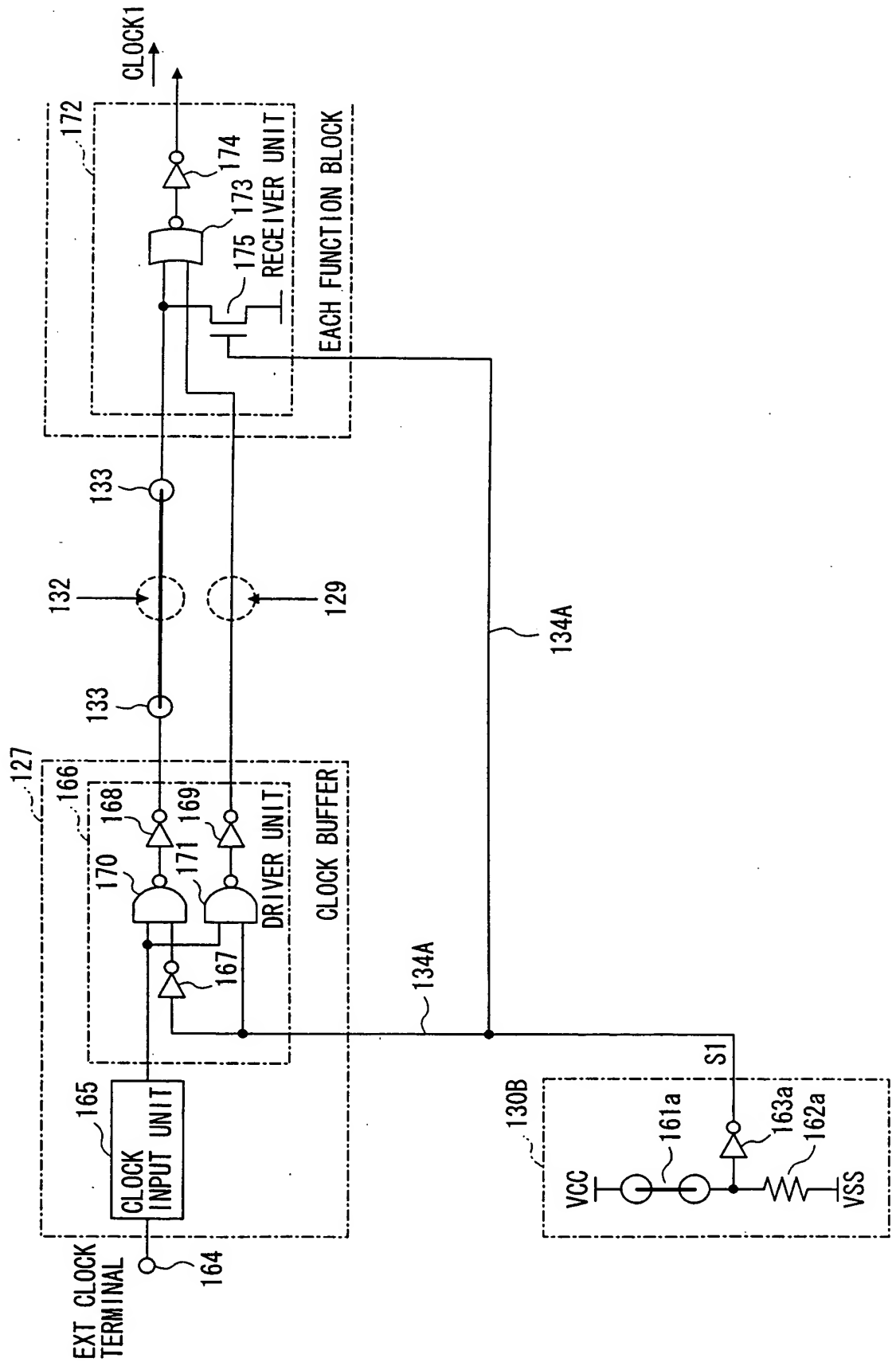


FIG.6

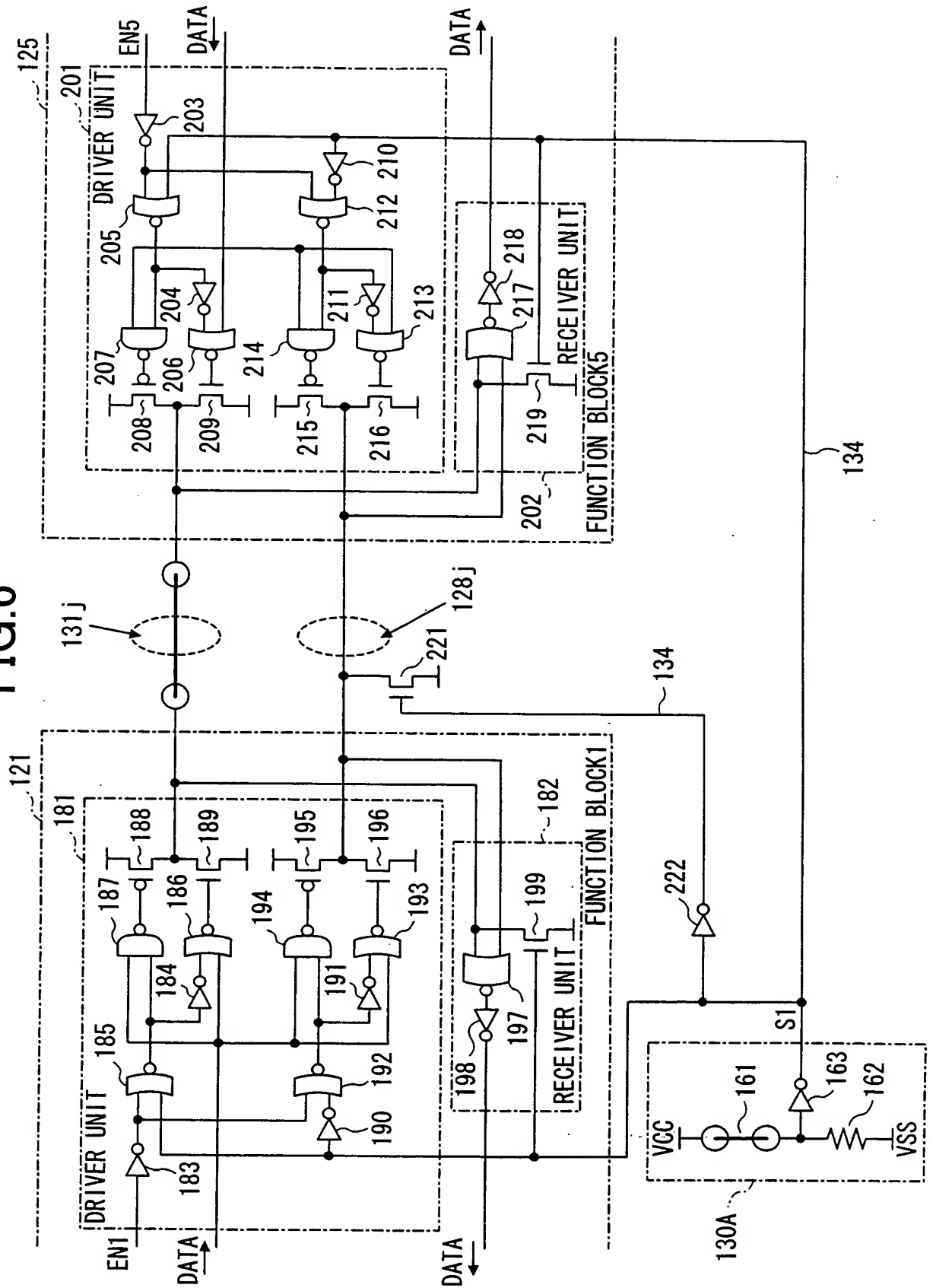


FIG.7A

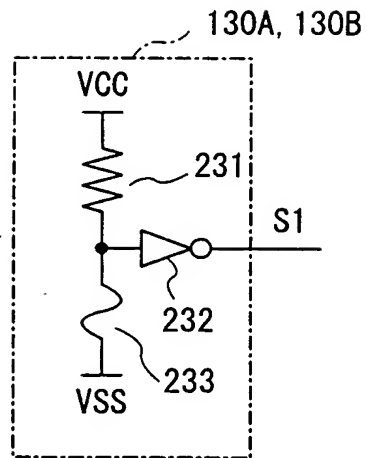


FIG.7B

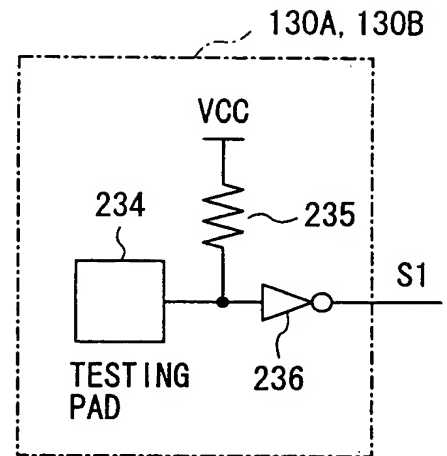


FIG.7C

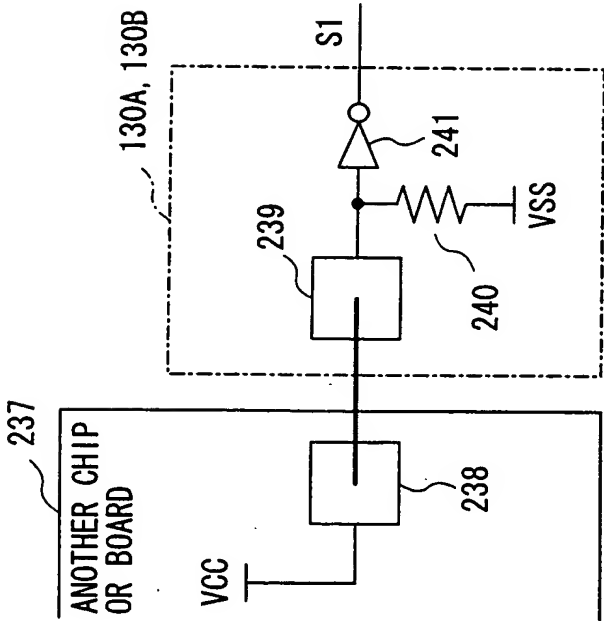


FIG.7D

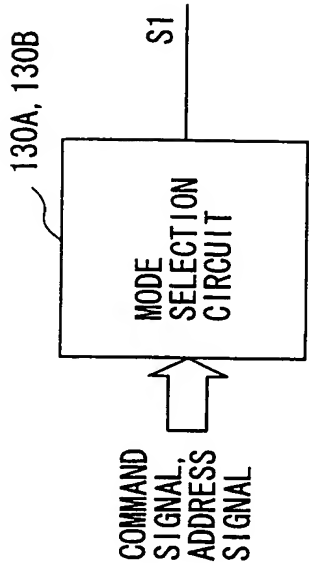




FIG.8

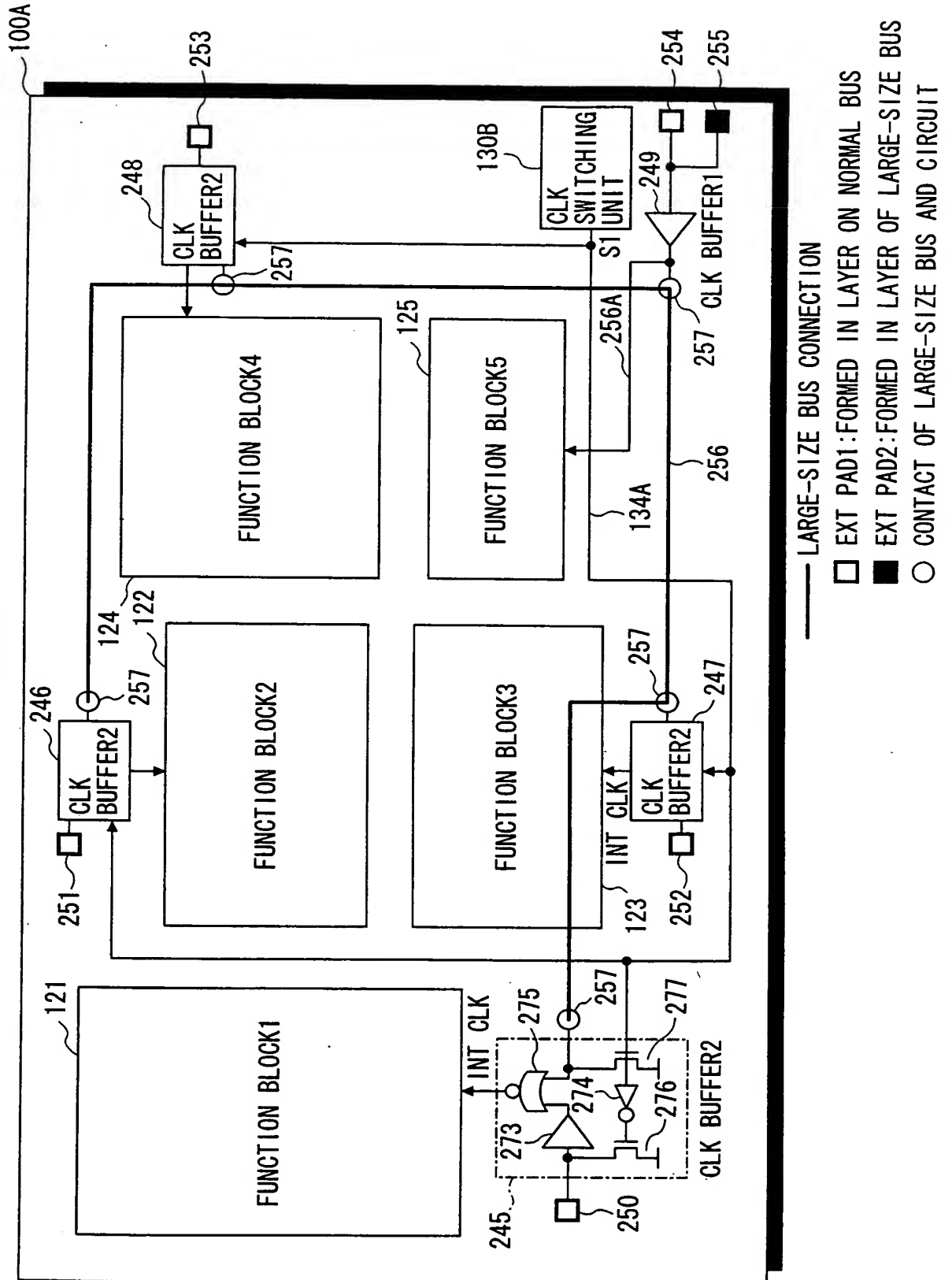
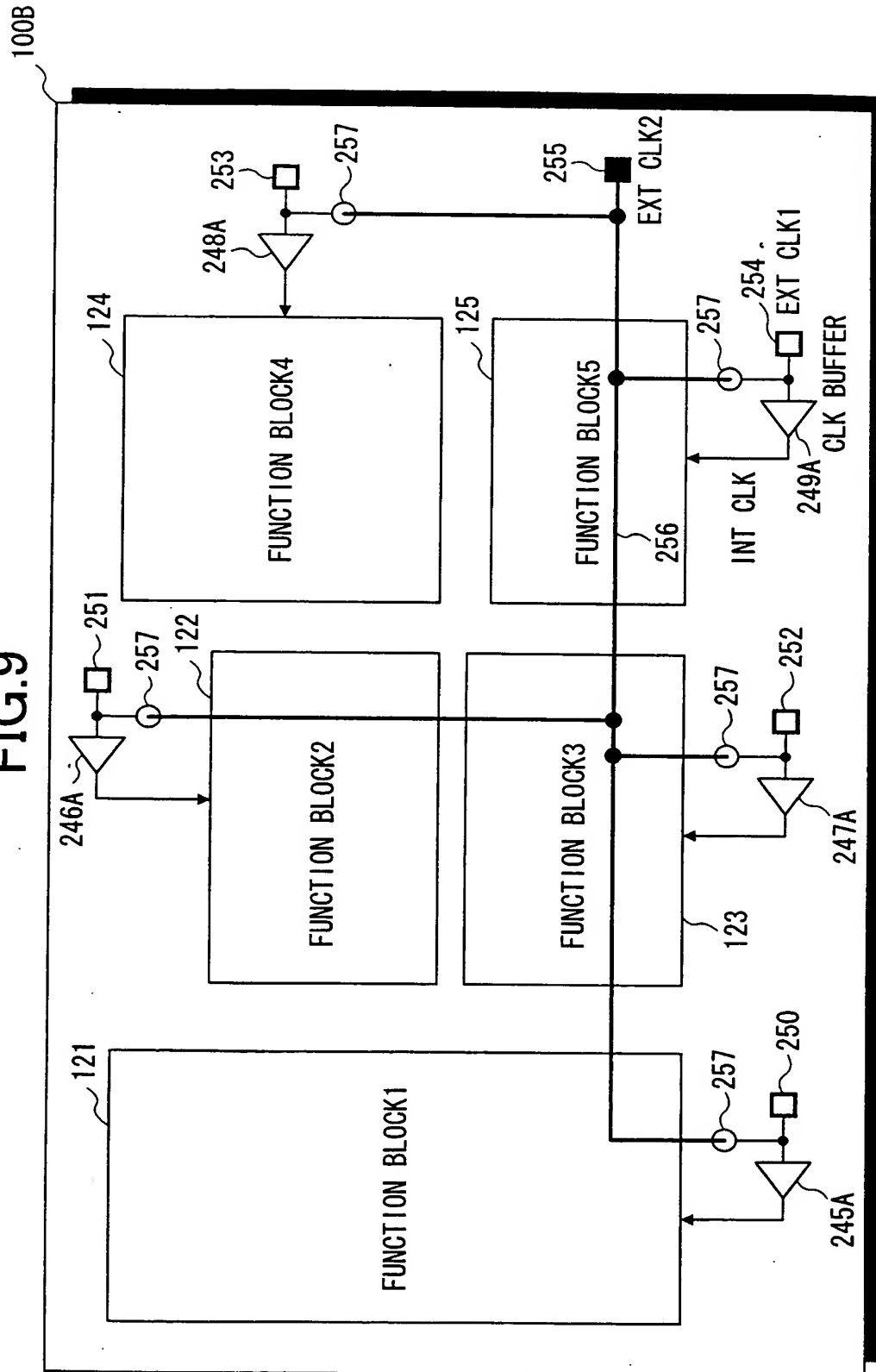


FIG.9



- LARGE-SIZE BUS CONNECTION
- EXT PAD1: FORMED IN LAYER ON NORMAL BUS
- EXT PAD2: FORMED IN LAYER OF LARGE-SIZE BUS
- CONTACT OF LARGE-SIZE BUS AND CIRCUIT

FIG.10

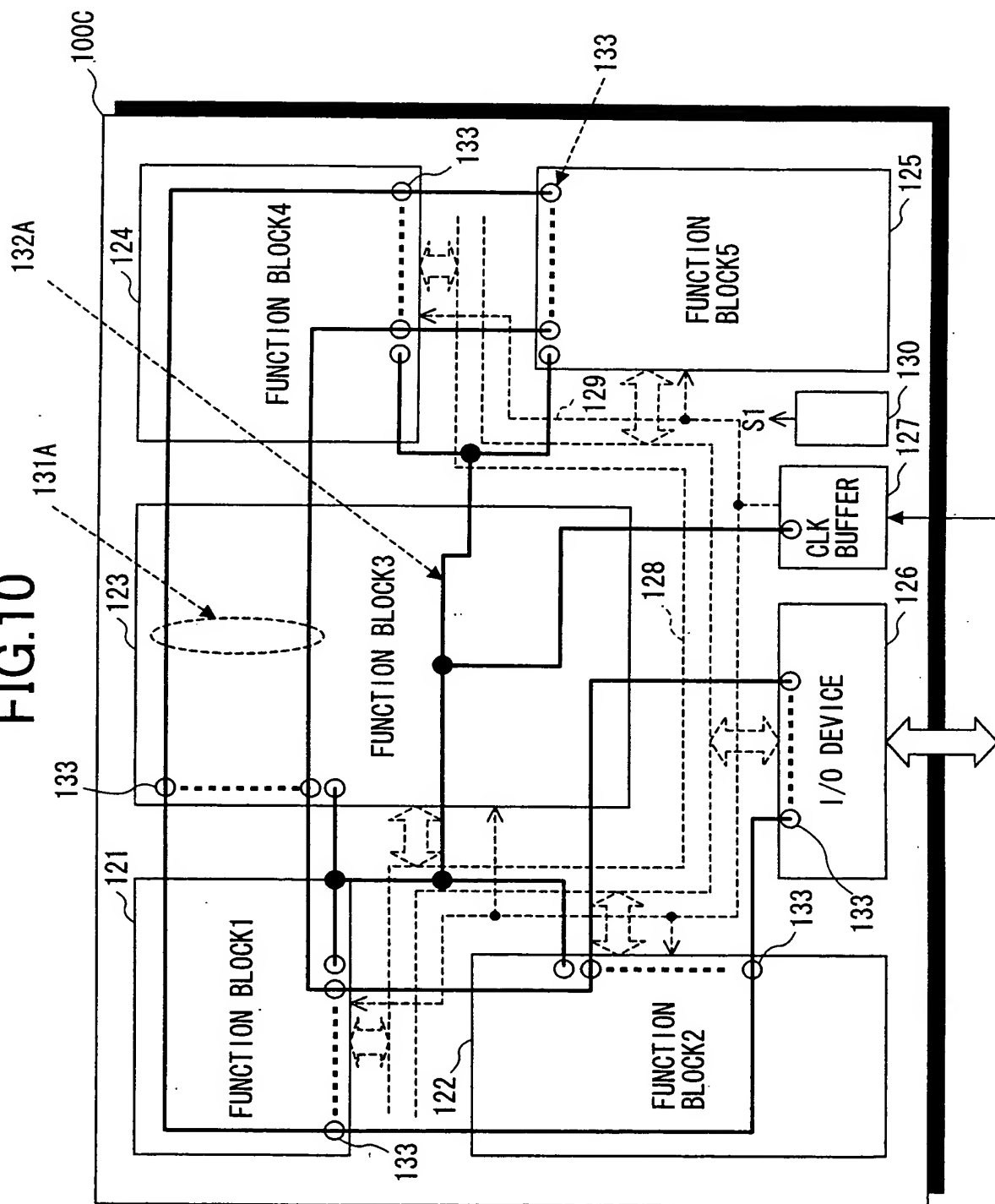
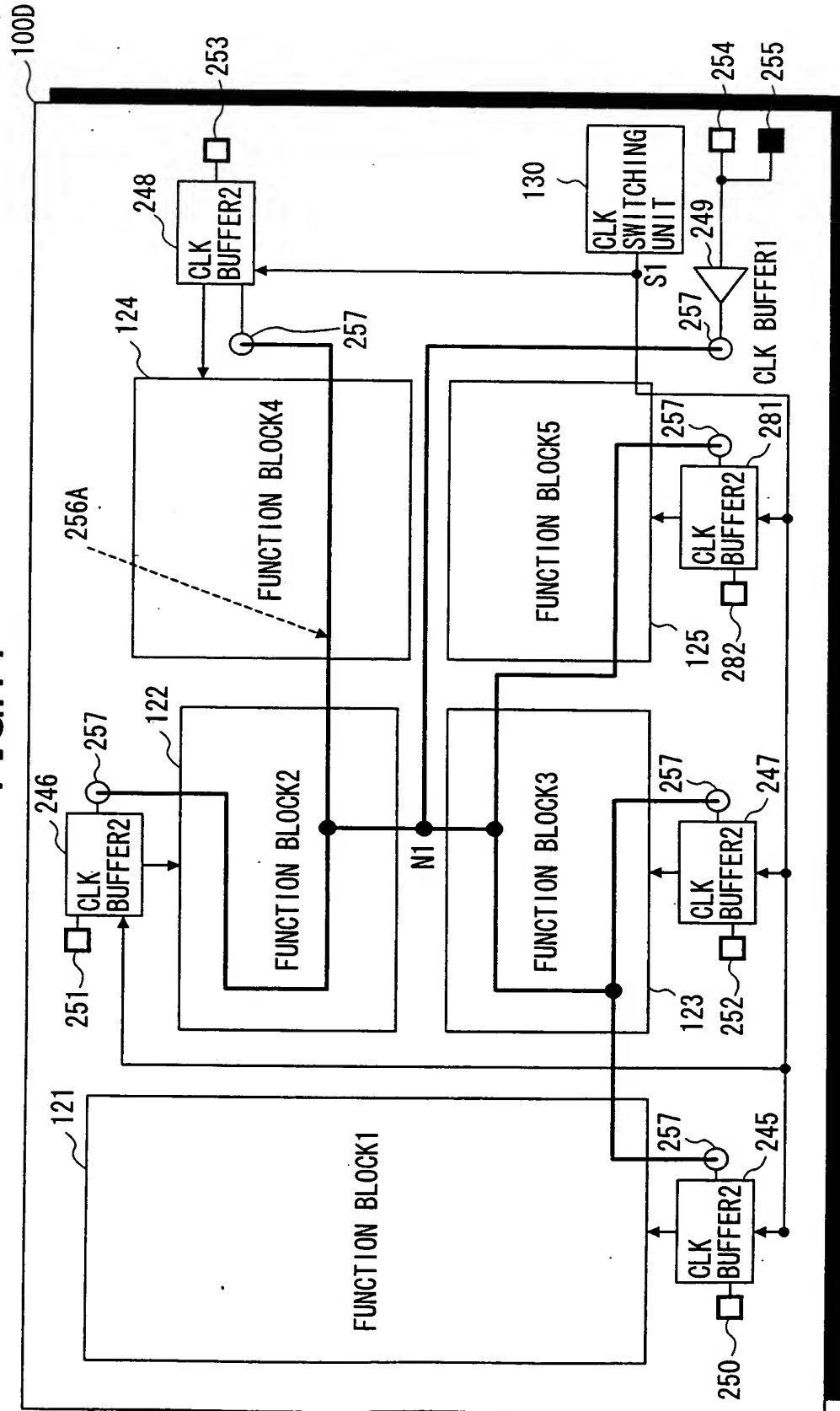


FIG.11



- LARGE-SIZE BUS CONNECTION
- EXT PAD1: FORMED IN LAYER ON NORMAL BUS
  - EXT PAD2: FORMED IN LAYER OF LARGE-SIZE BUS
  - CONTACT OF LARGE-SIZE BUS AND CIRCUIT

FIG.12

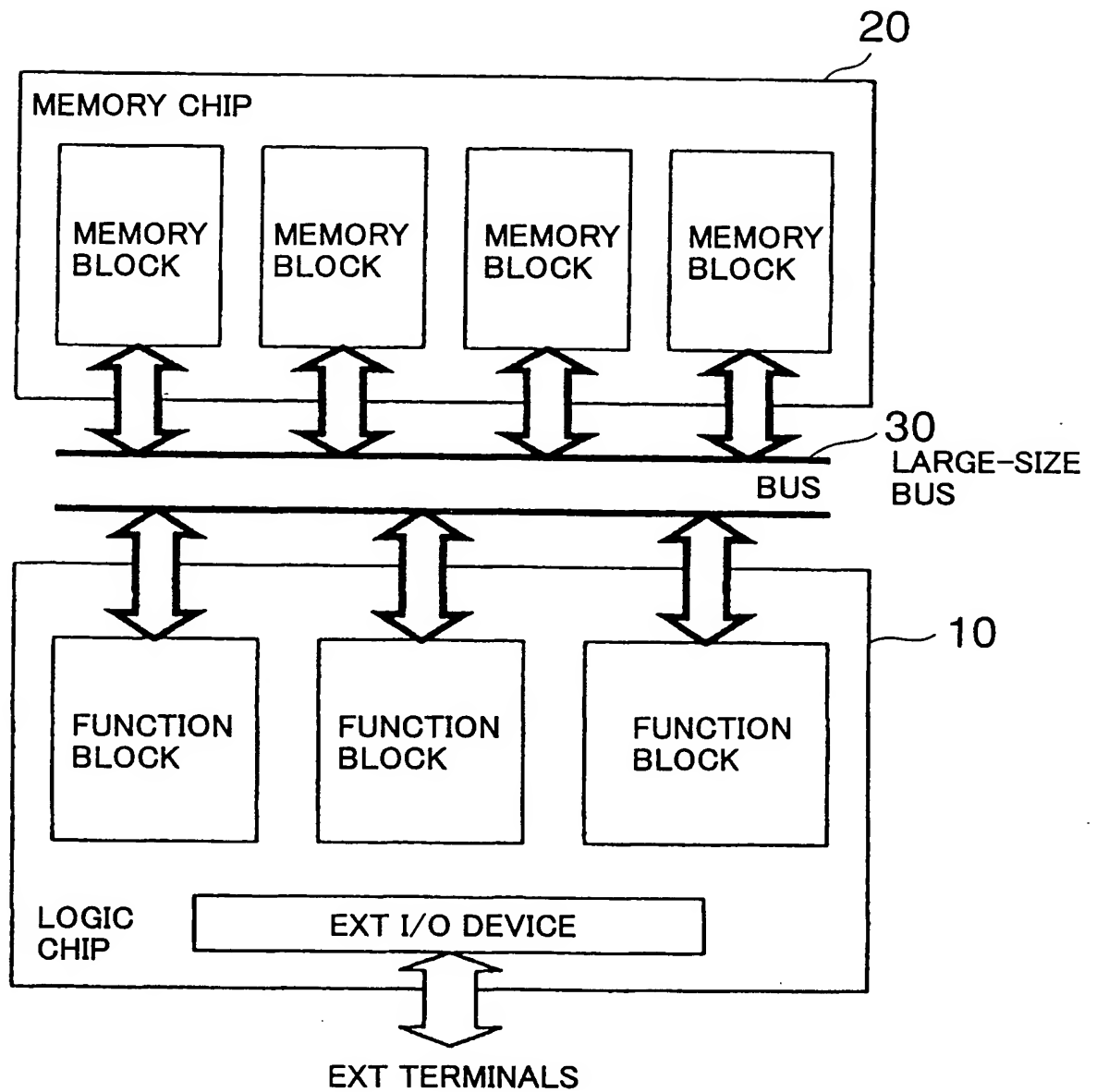


FIG.13

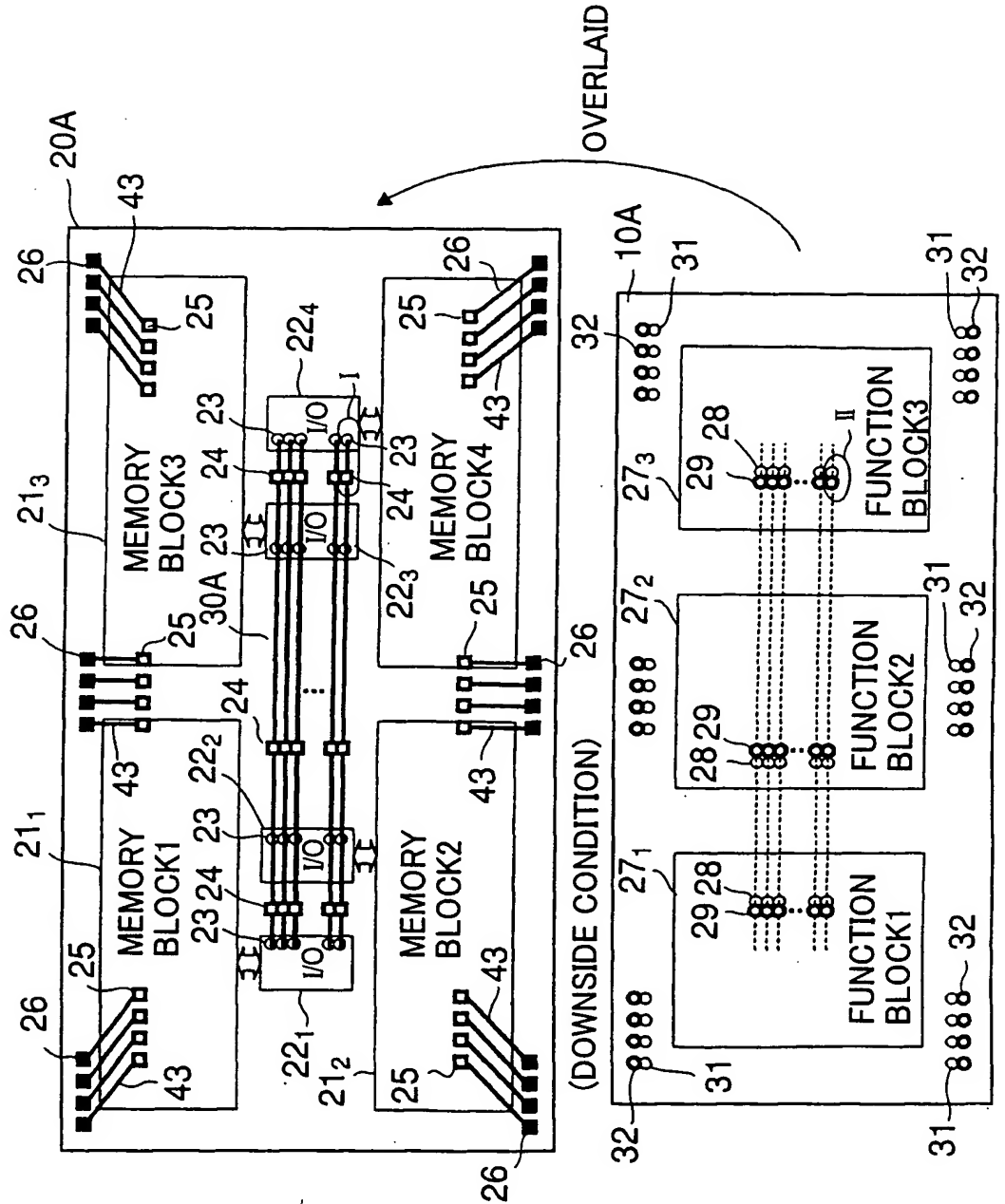


FIG. 14

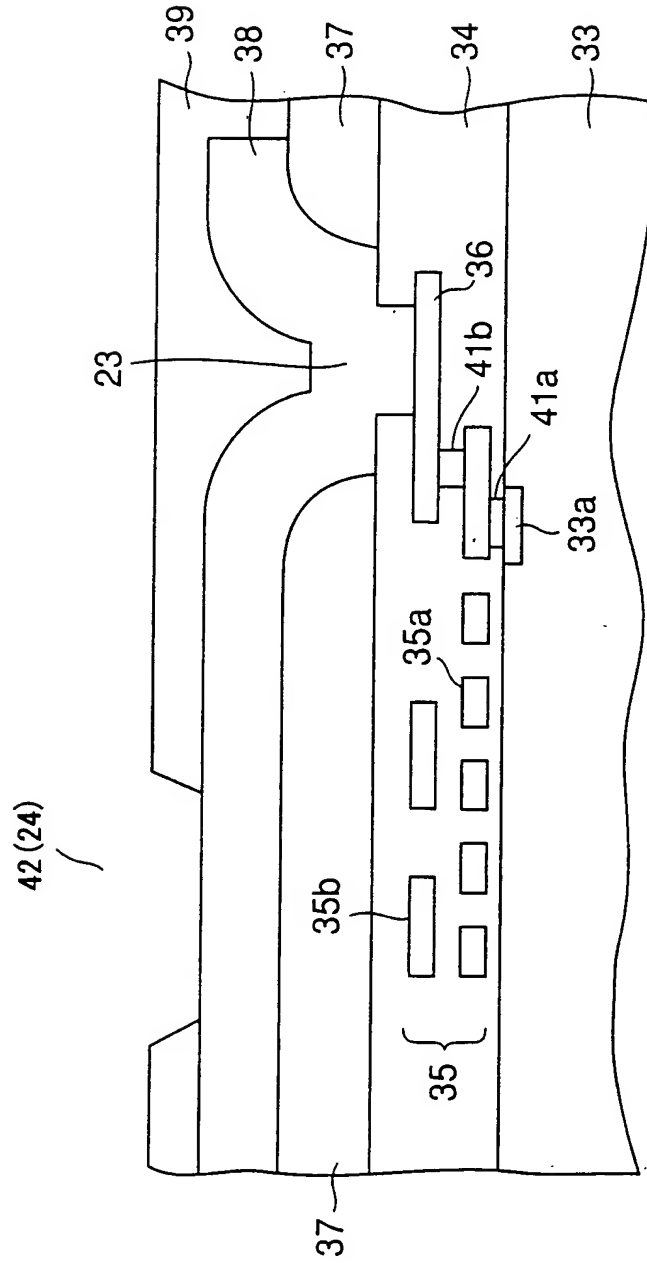
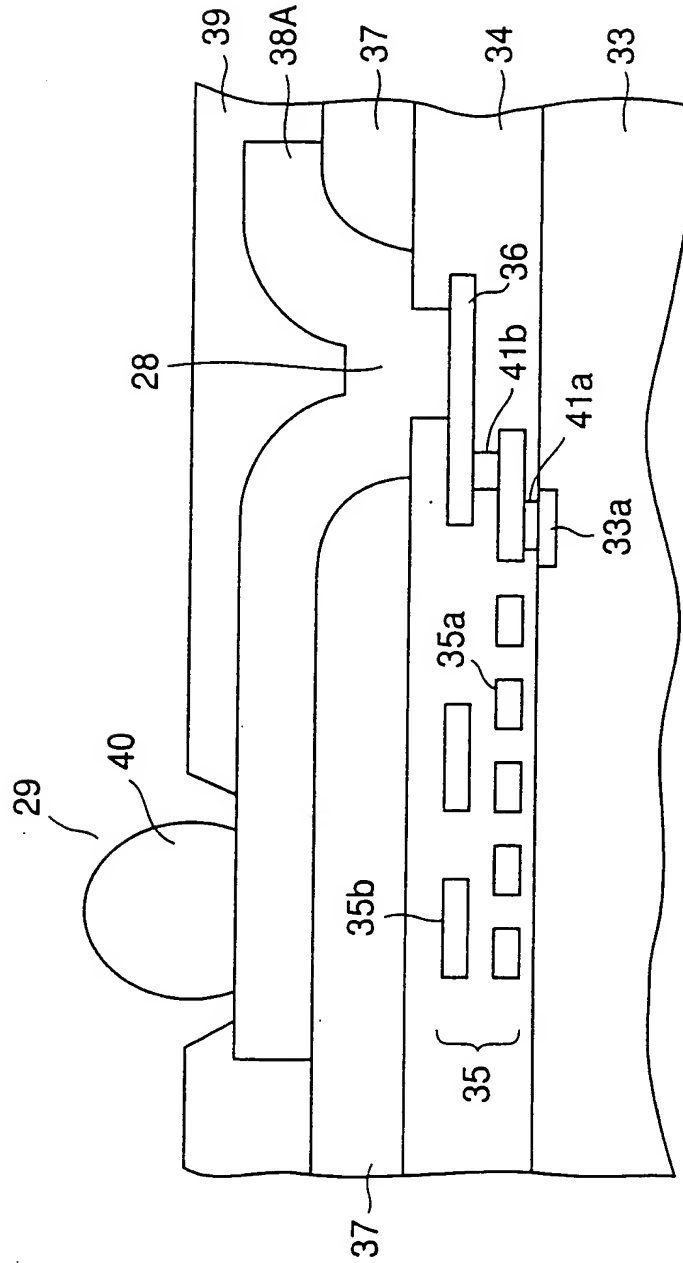


FIG. 15





Inventor: Yasurou MATSUZAKI  
Appln. No. : New Application  
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**FIG. 16**

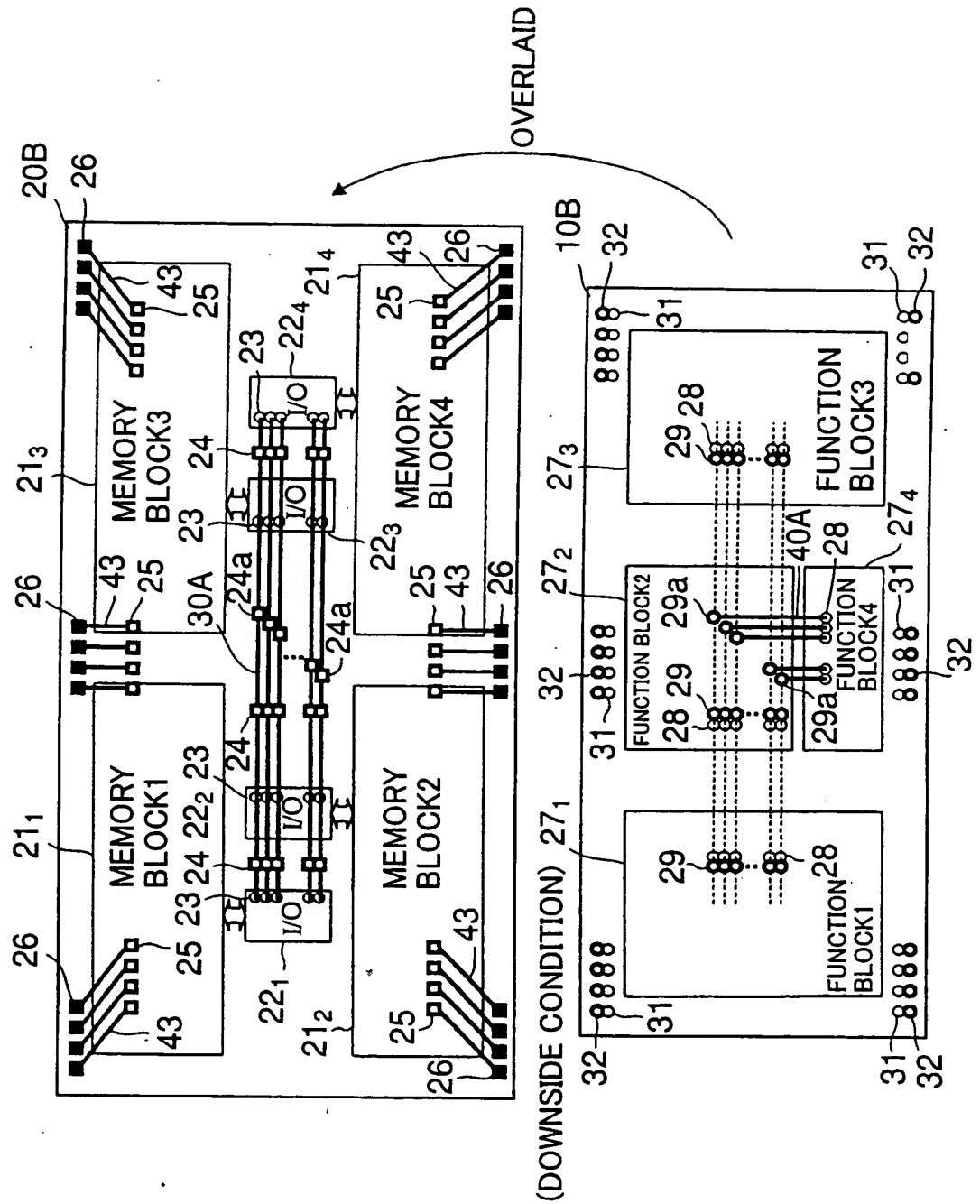


FIG.17

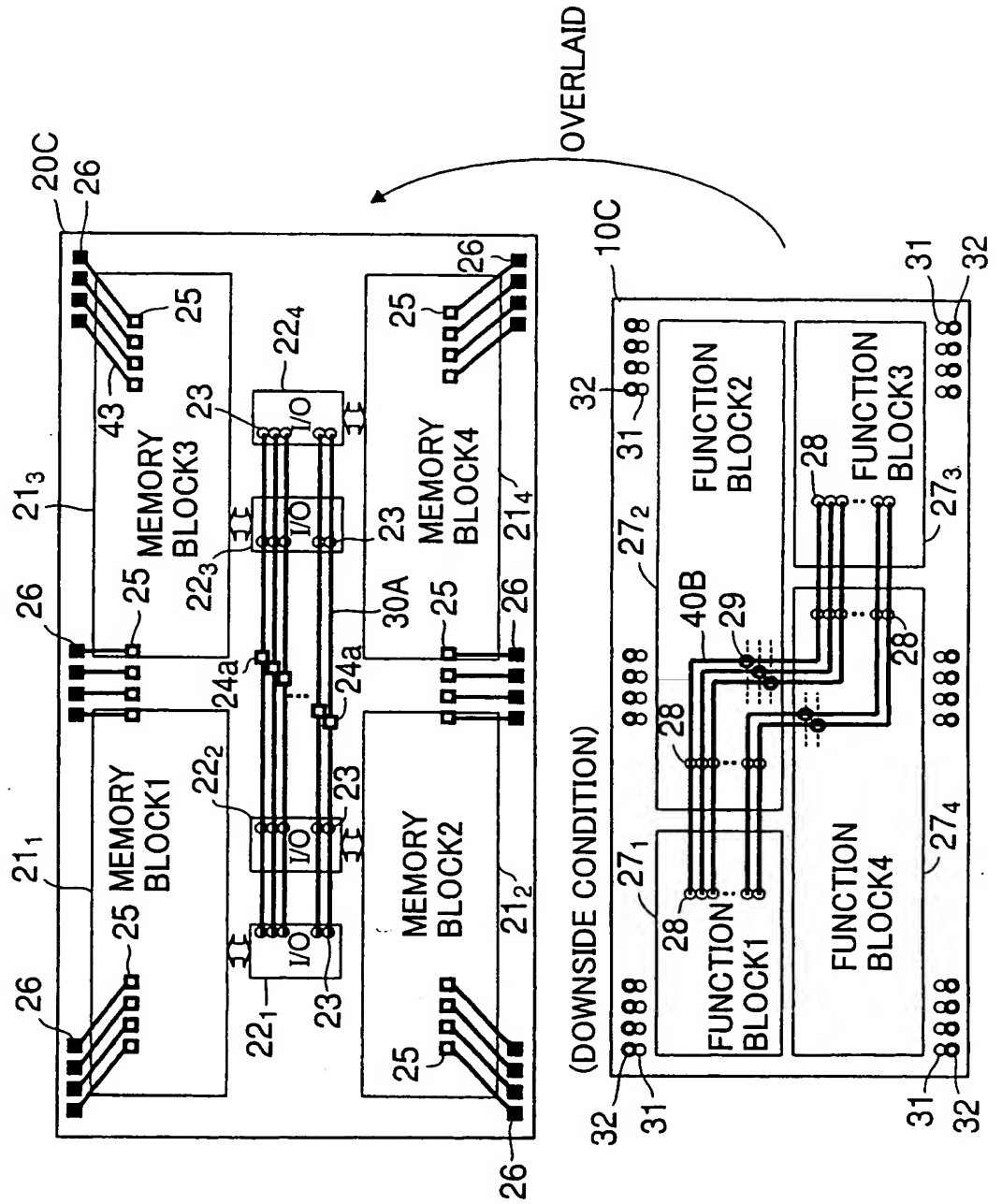


FIG.18

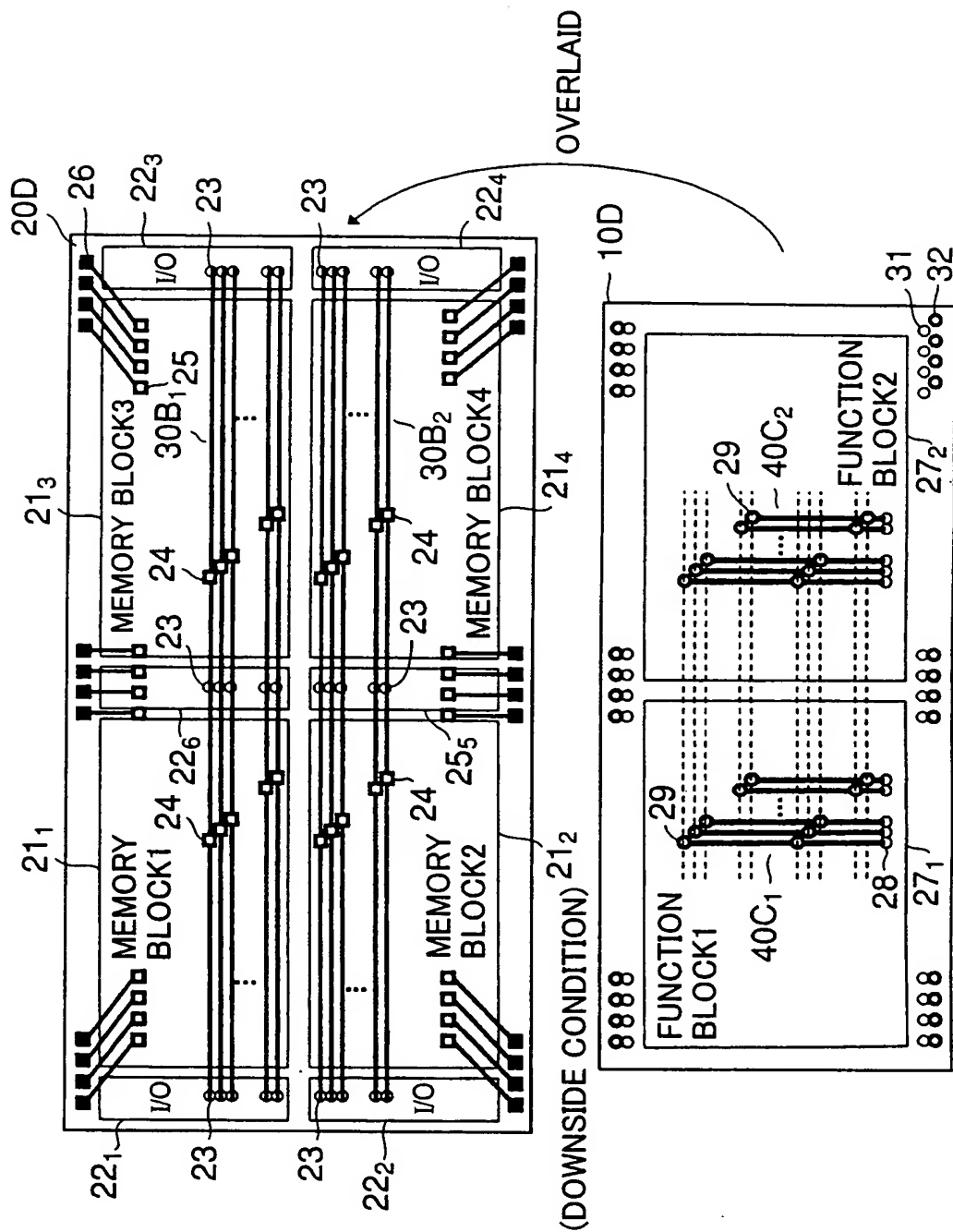


FIG.19

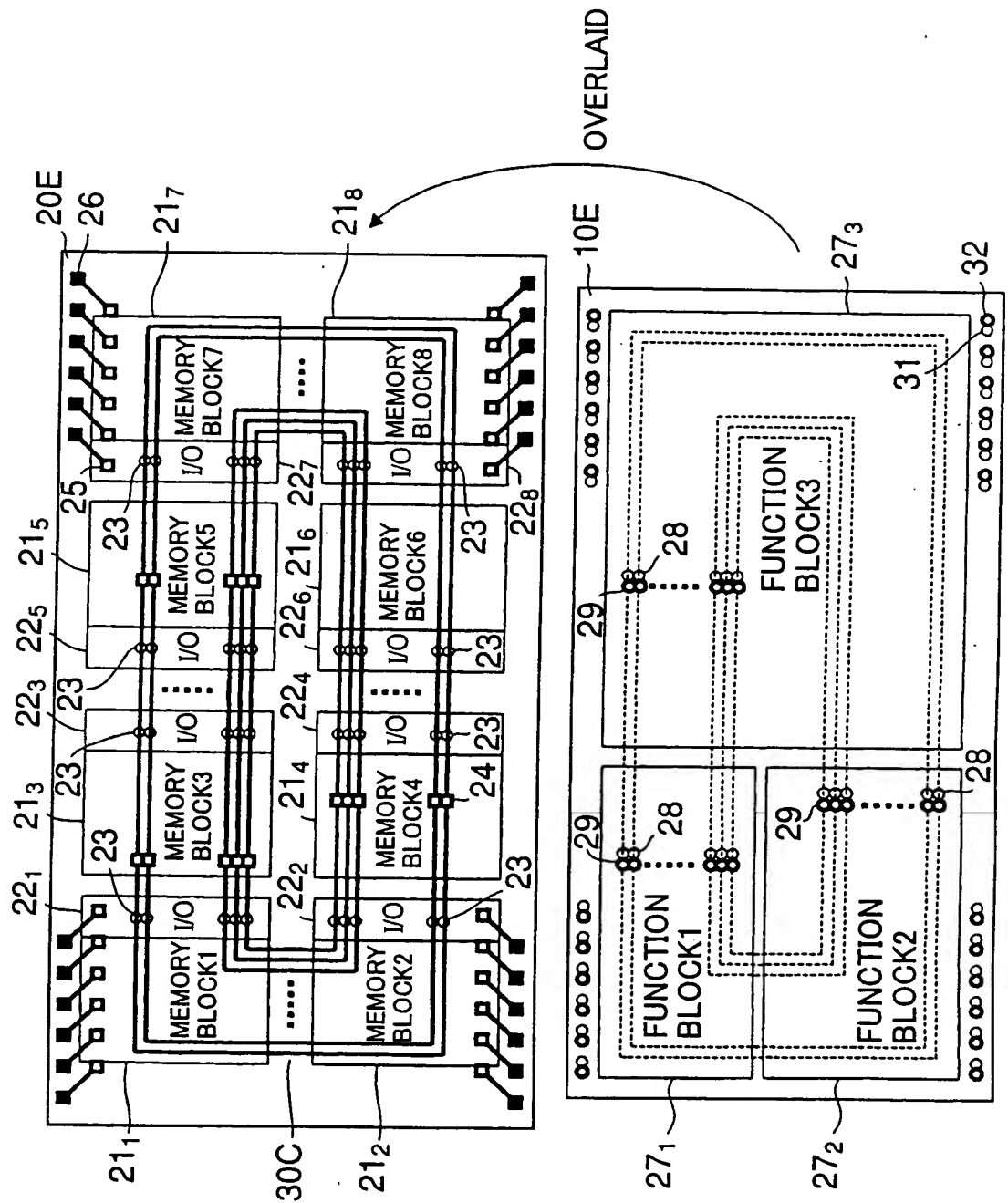


FIG.20

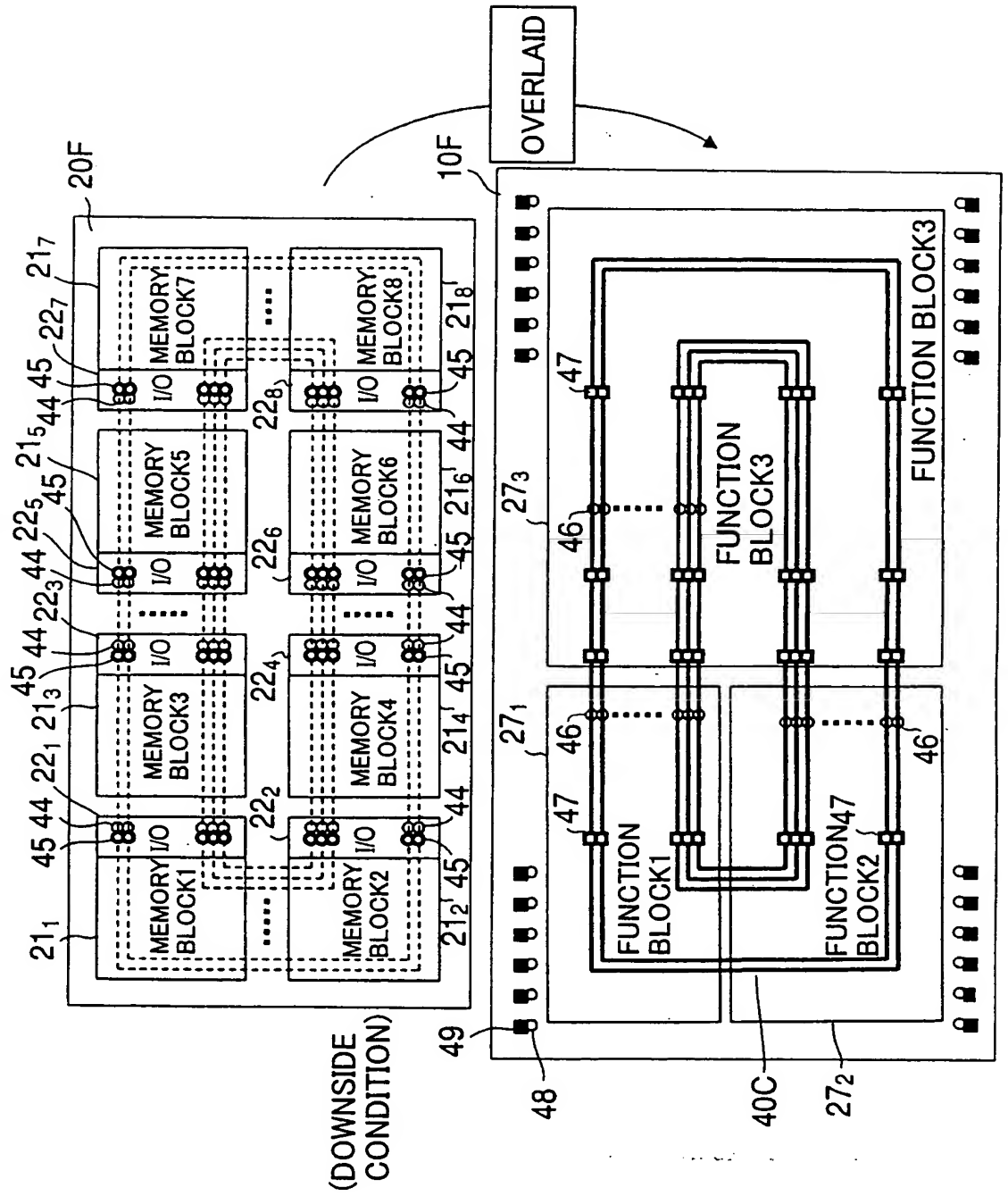
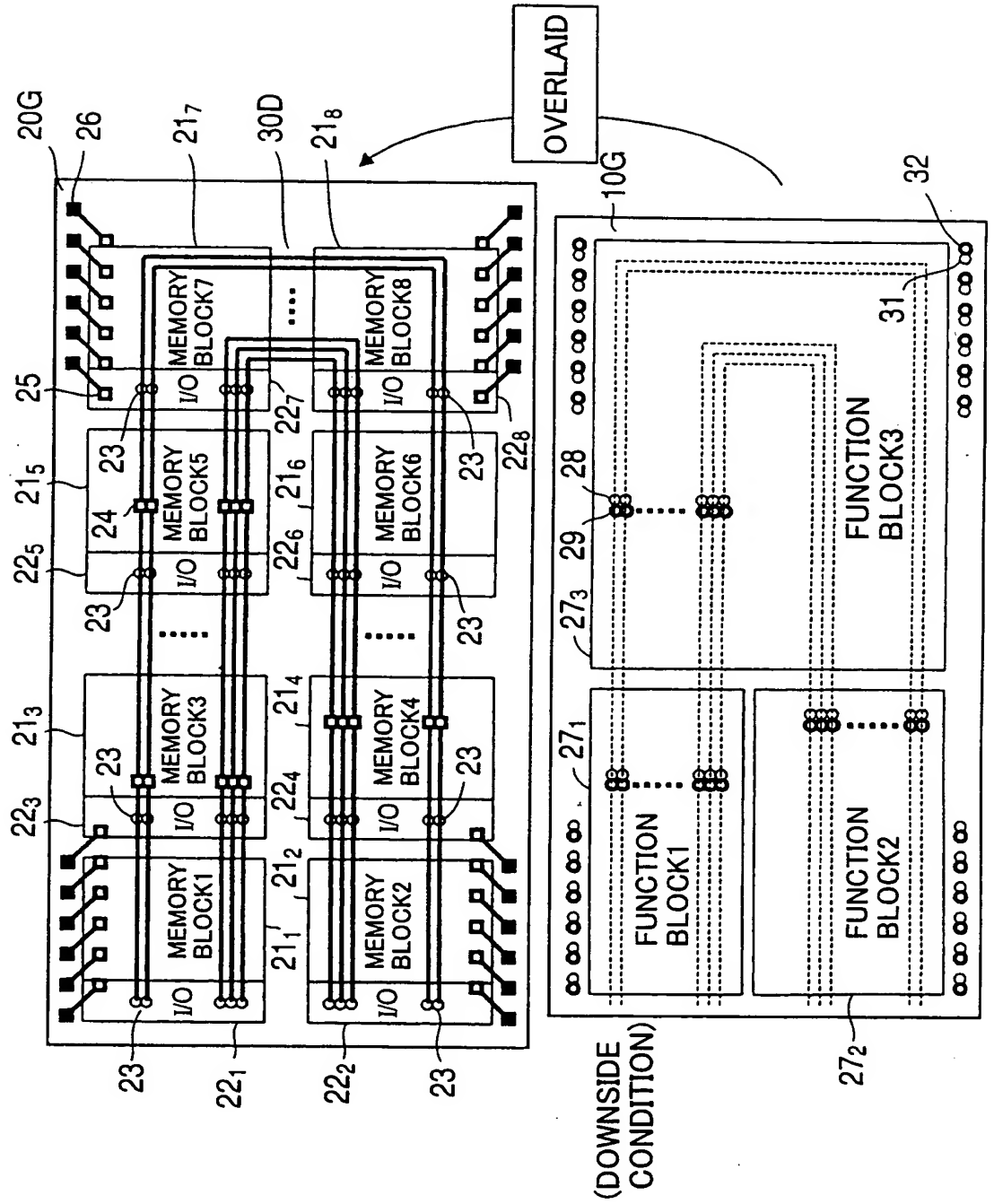


FIG.21



**FIG.22**

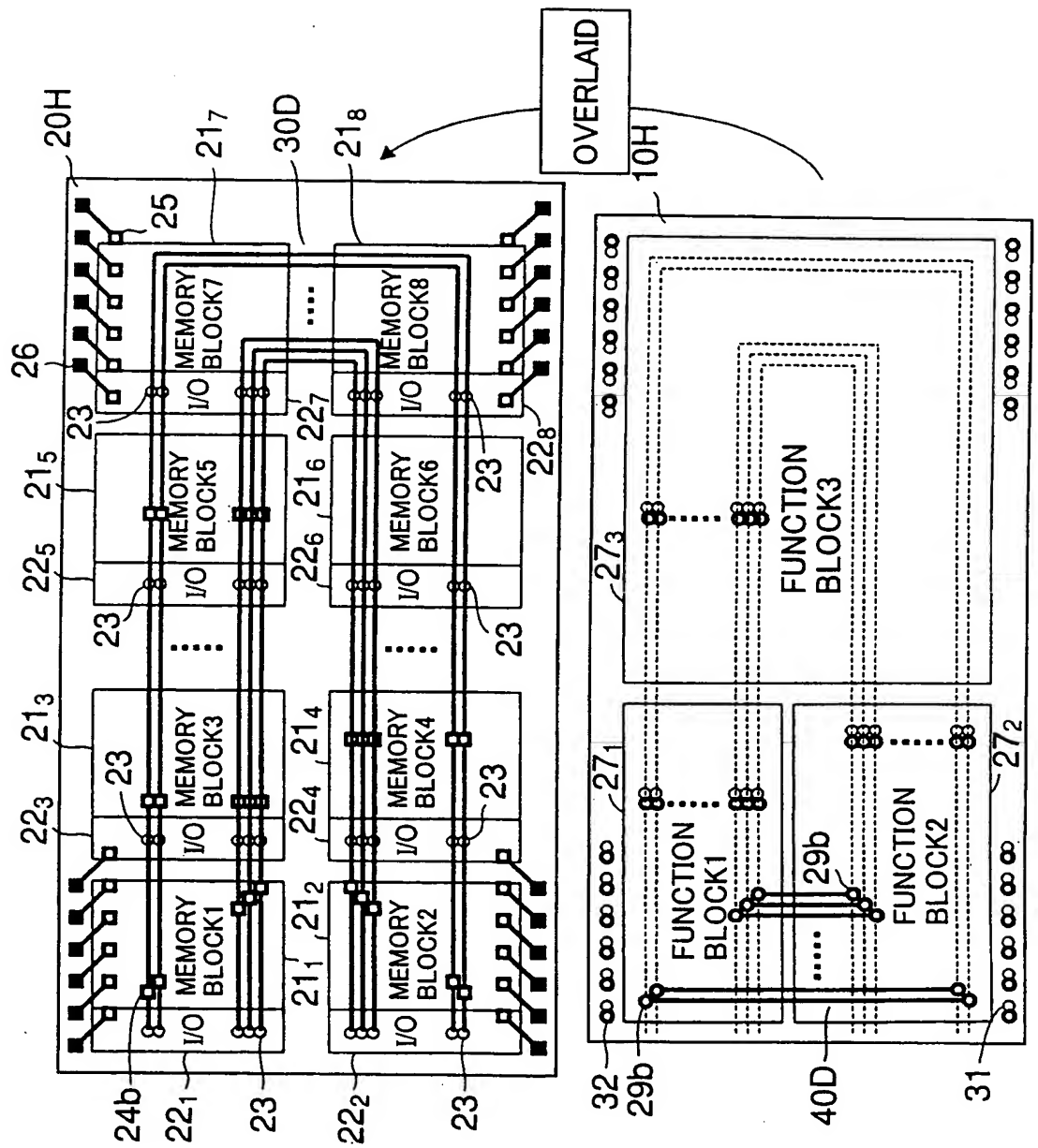


FIG.23

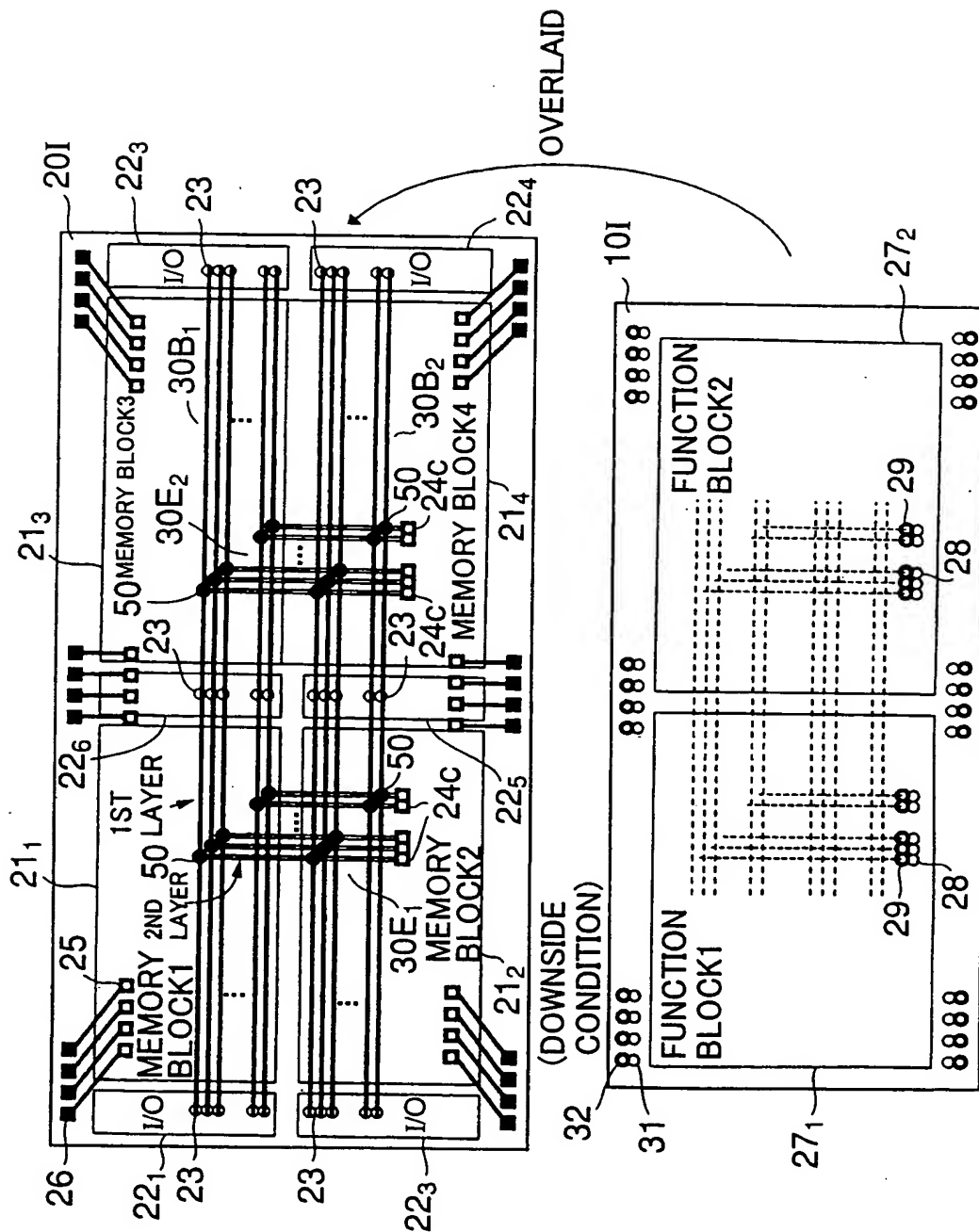




FIG. 24

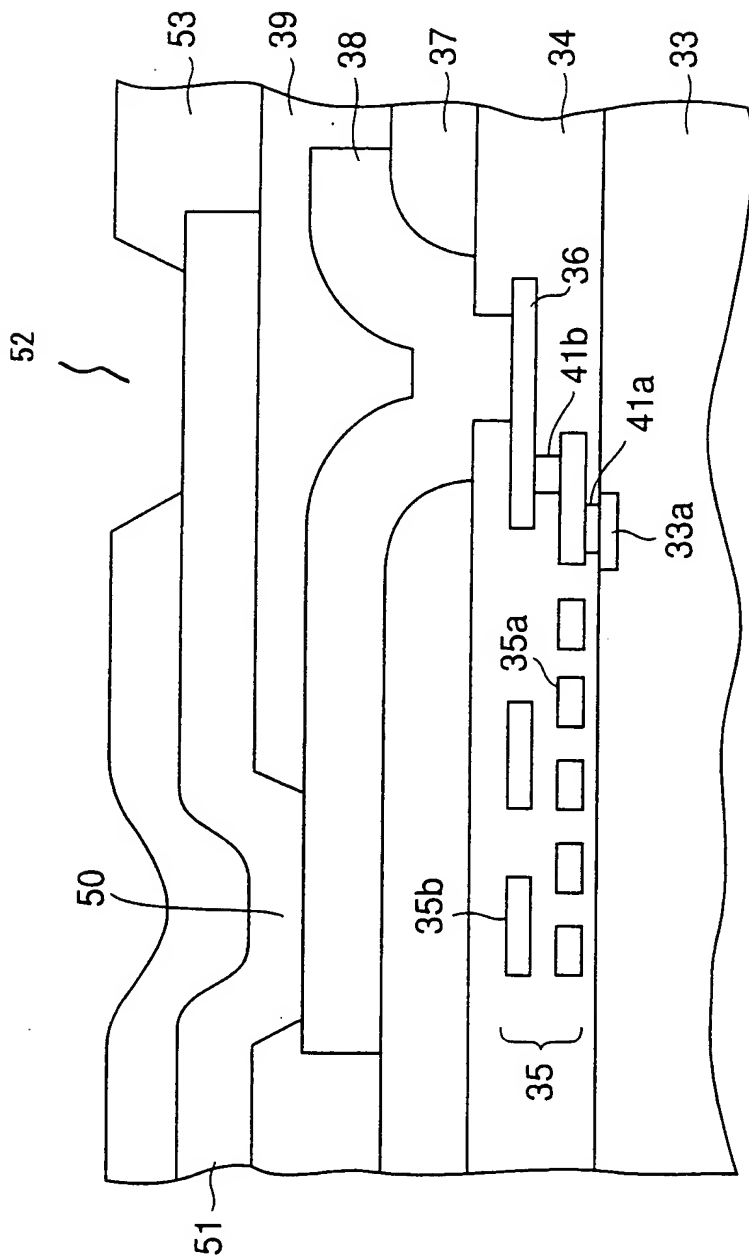


FIG.25

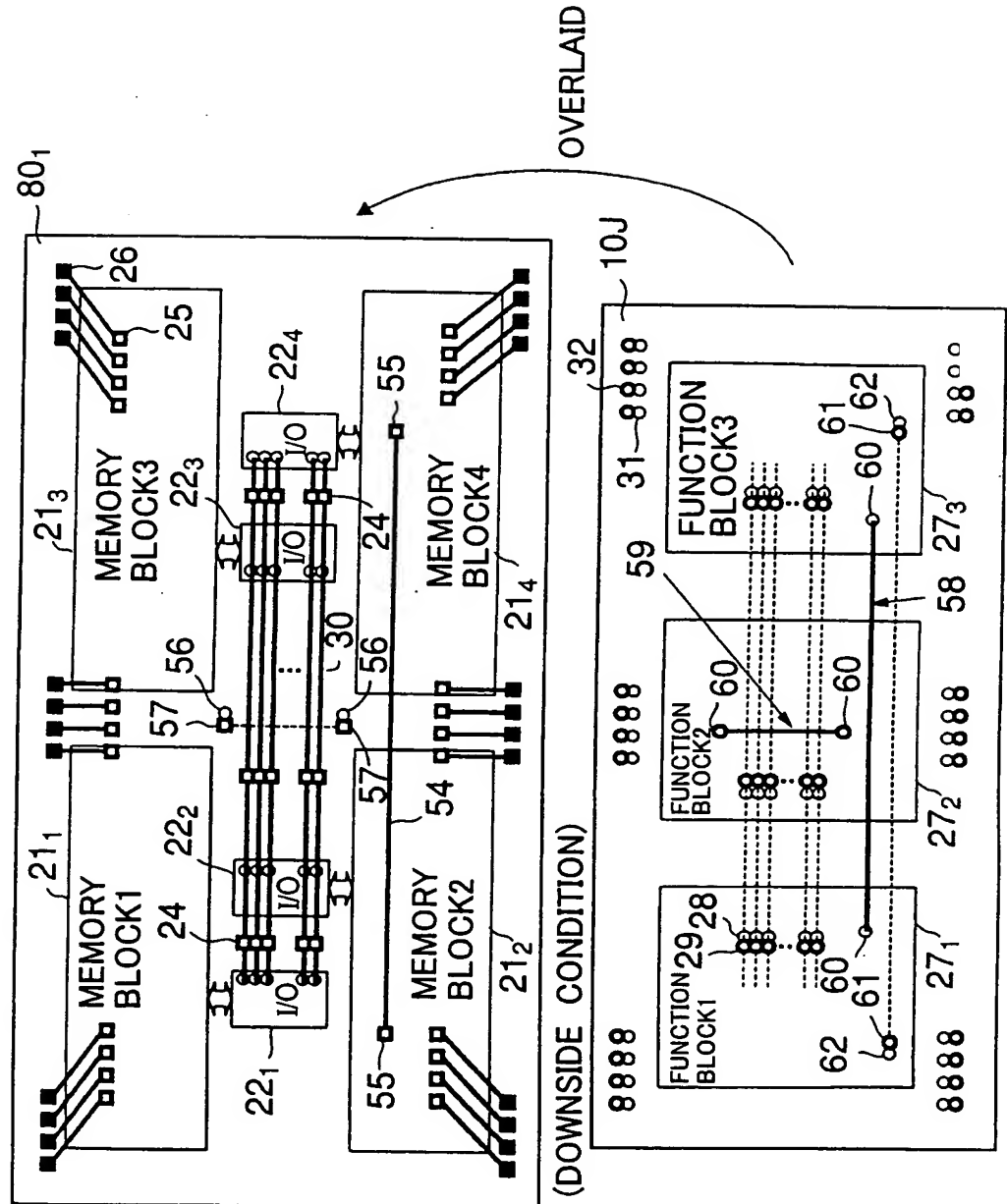


FIG.26

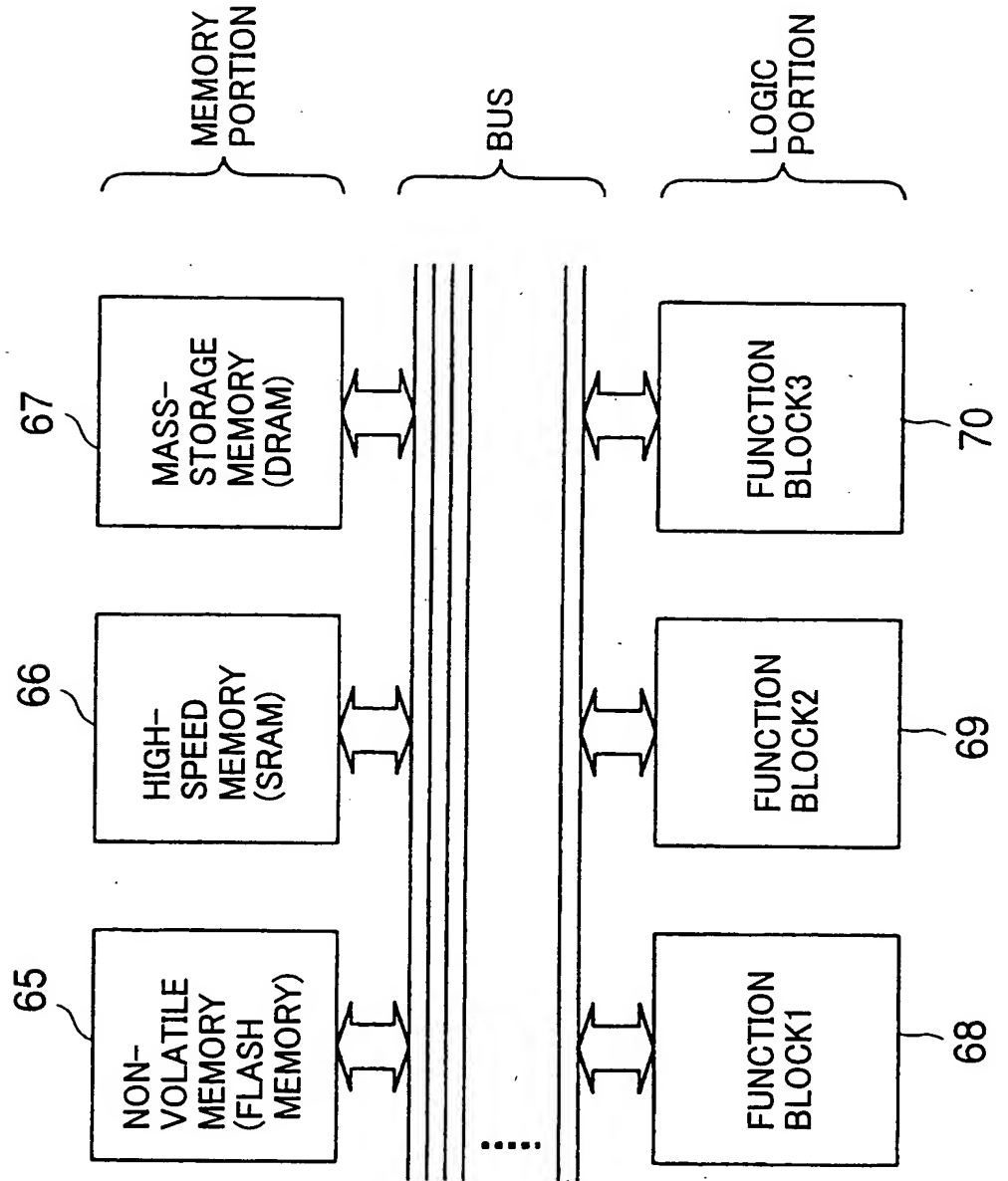


FIG.27

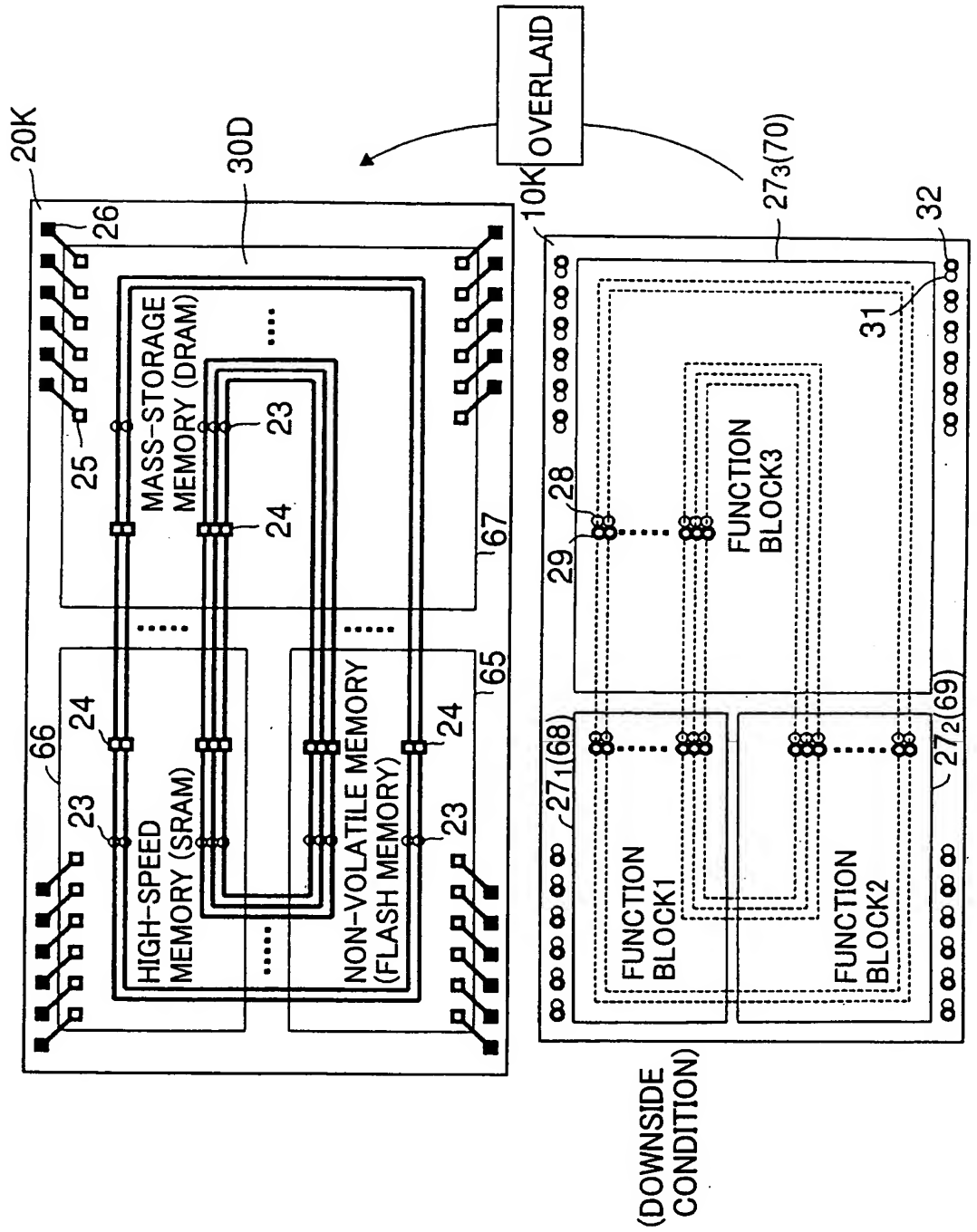


FIG.28

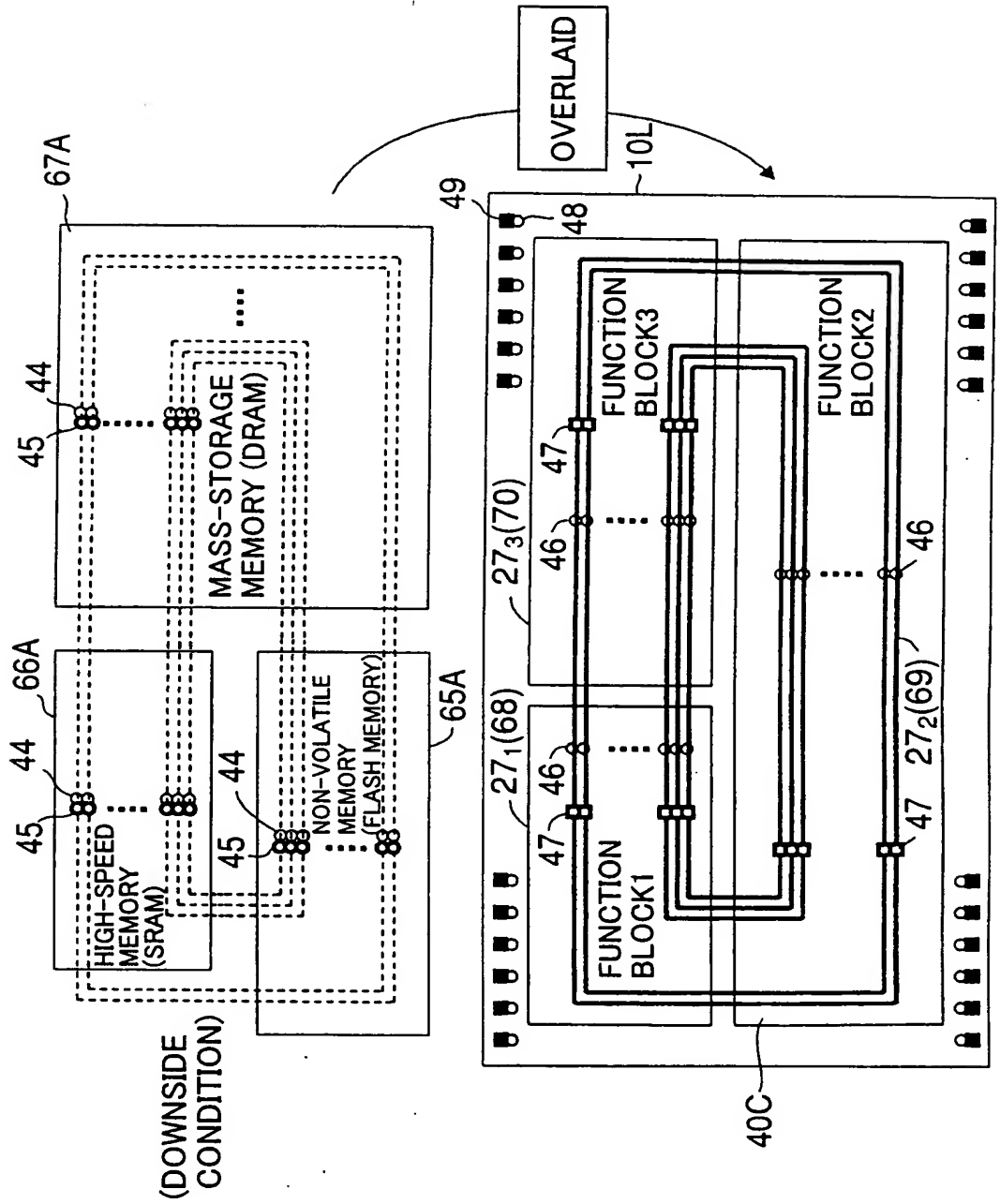


FIG.29

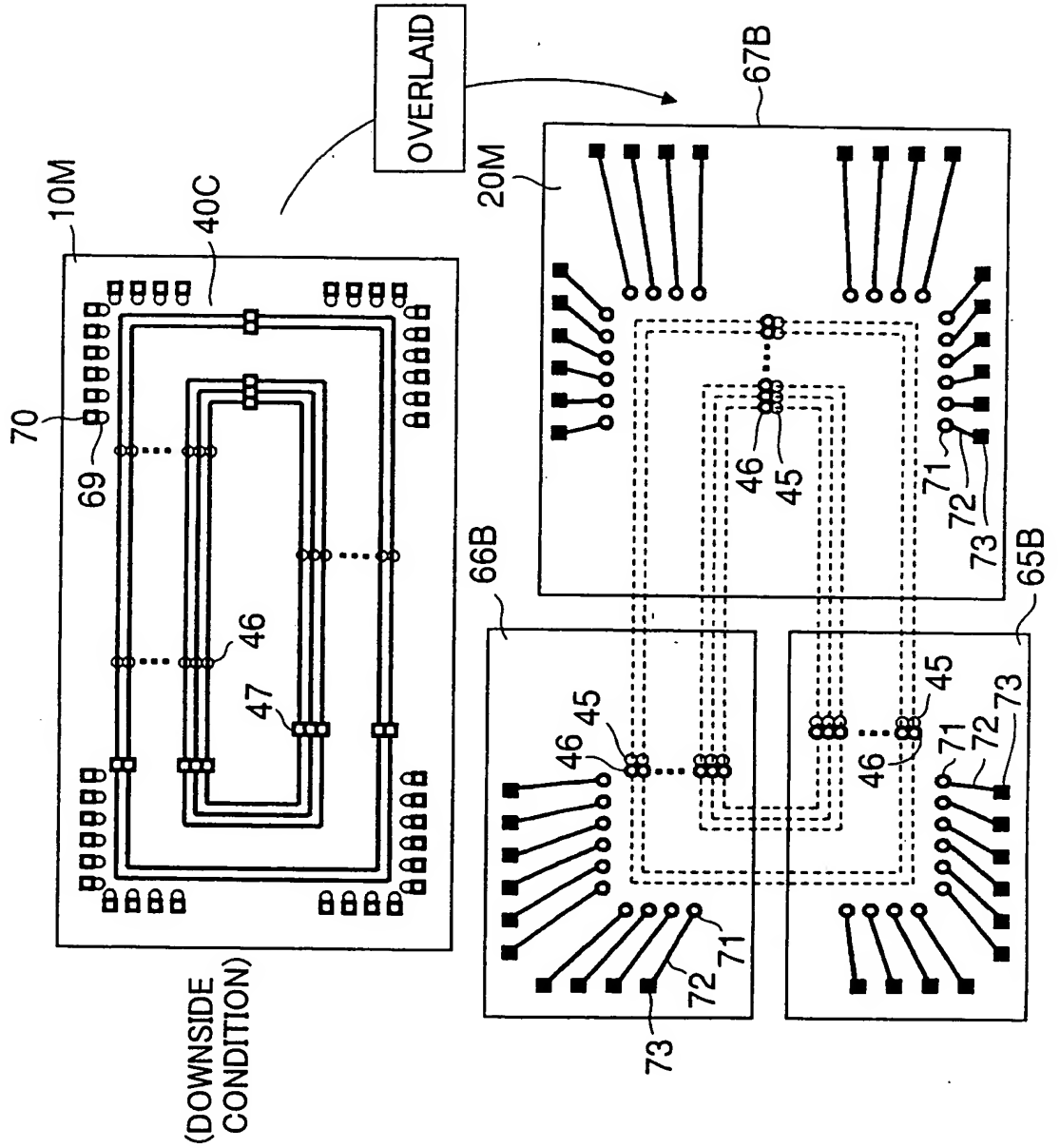


FIG. 30

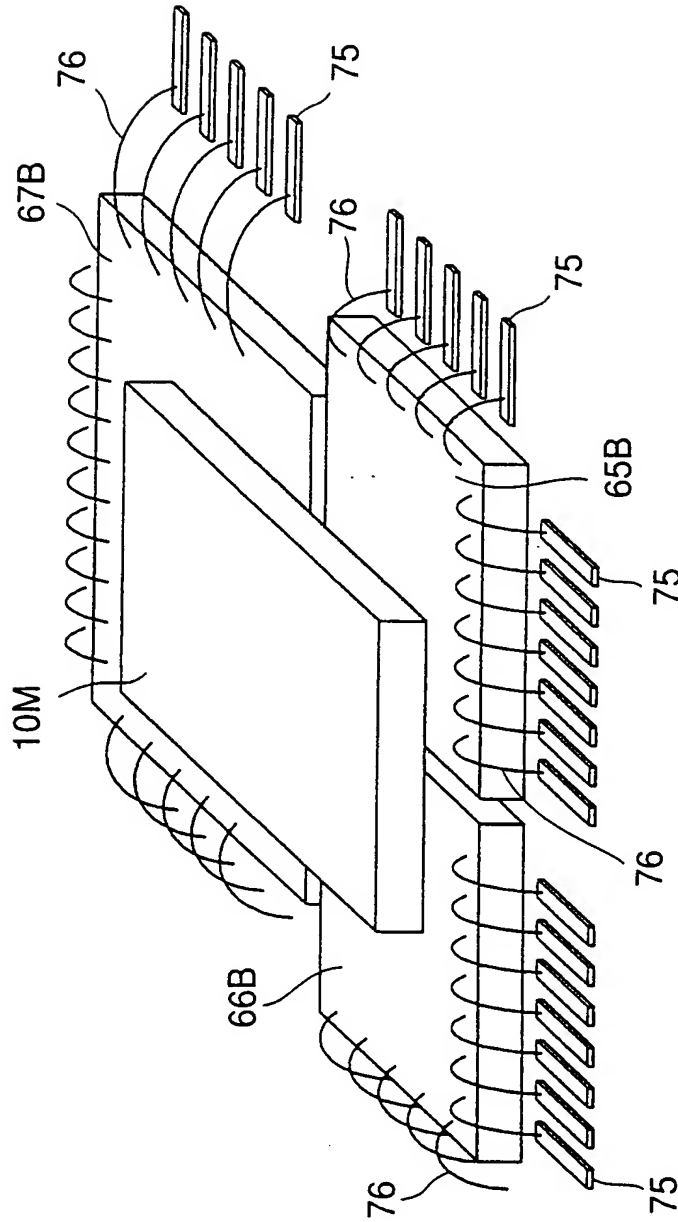


FIG. 31

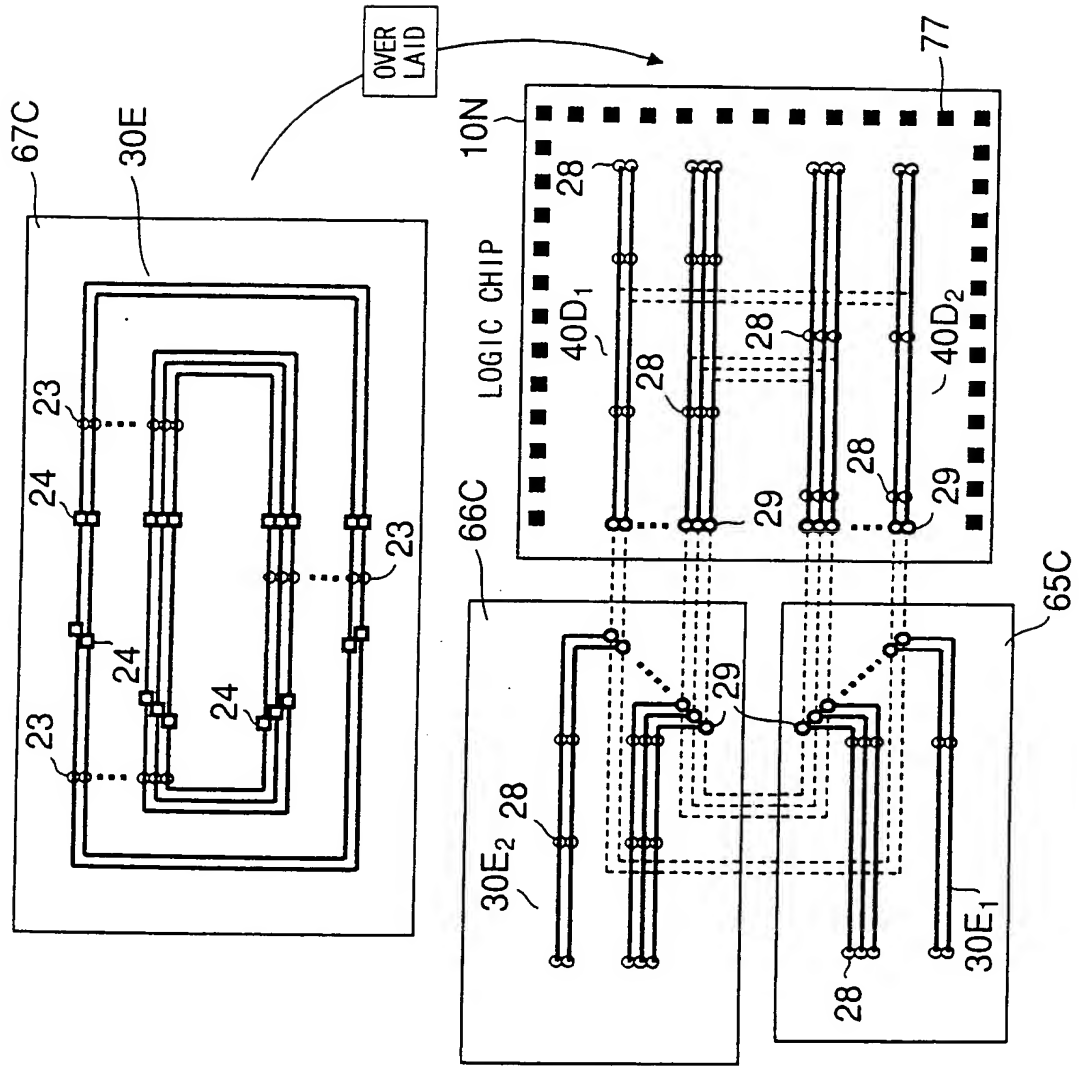




FIG. 32

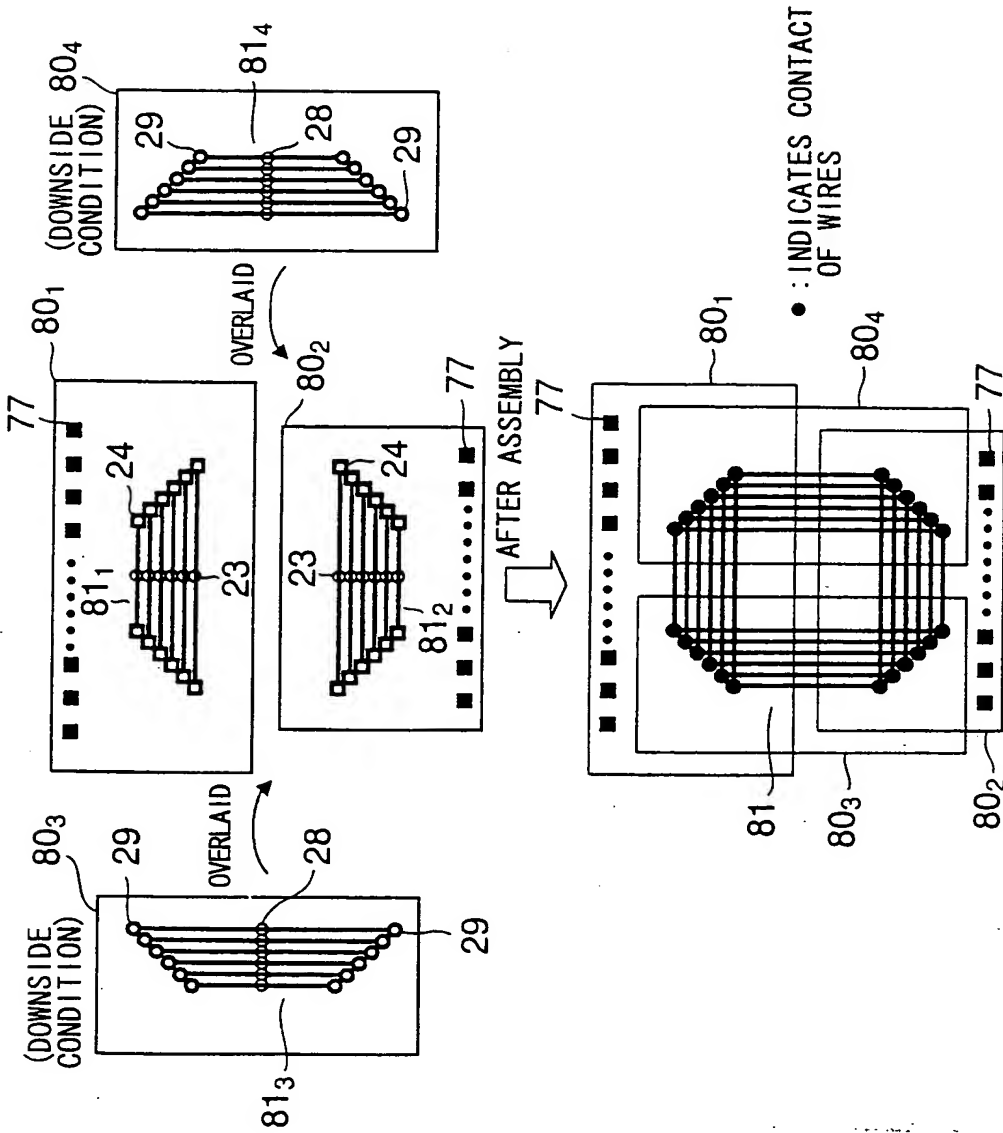


FIG. 33

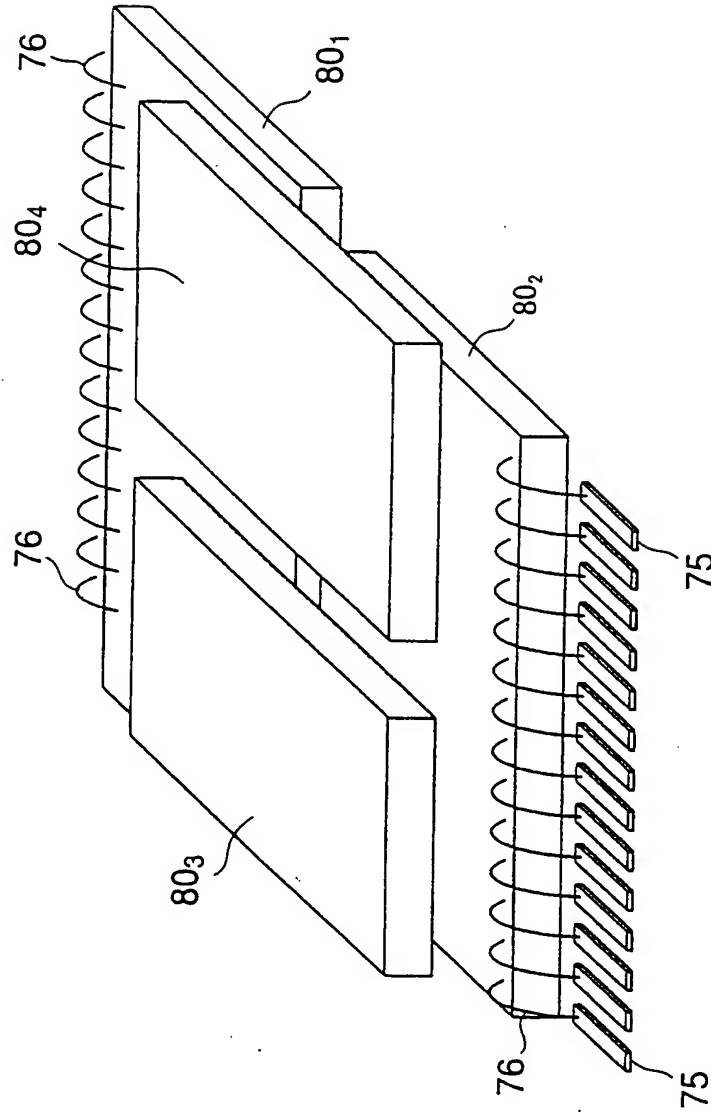
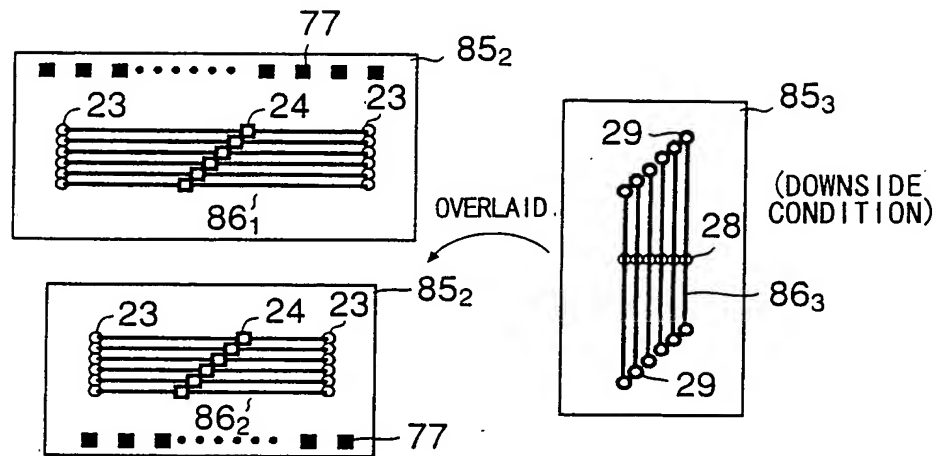


FIG. 34A



AFTER ASSEMBLY

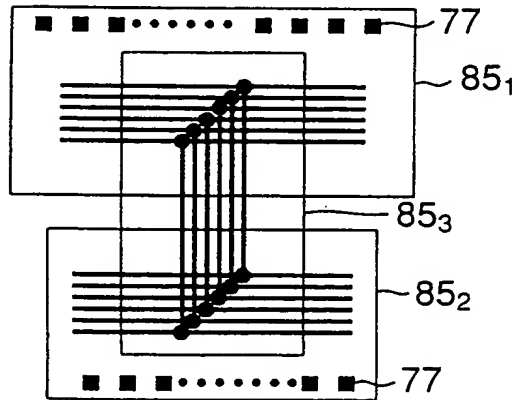


FIG. 34B

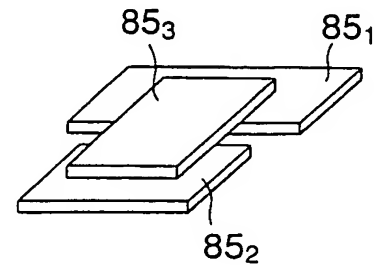


FIG.35

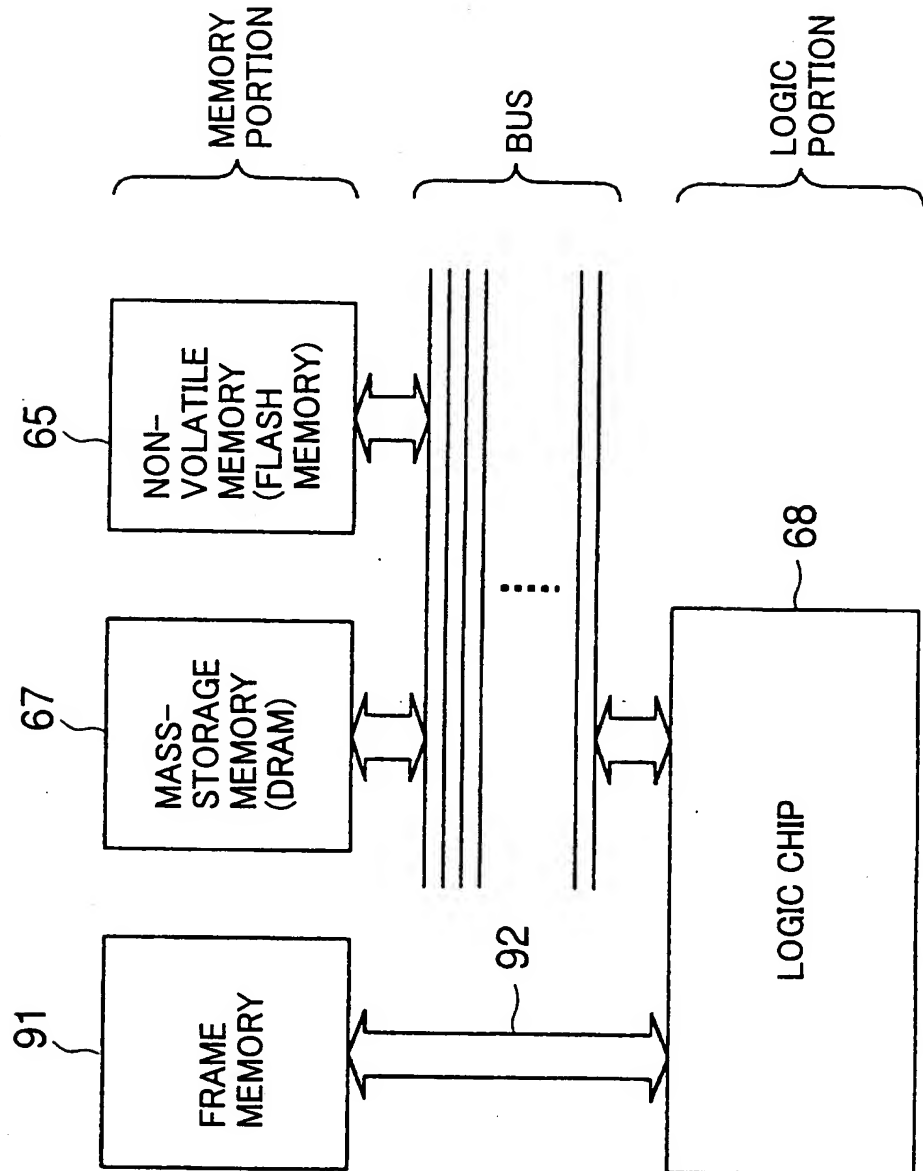


FIG. 36

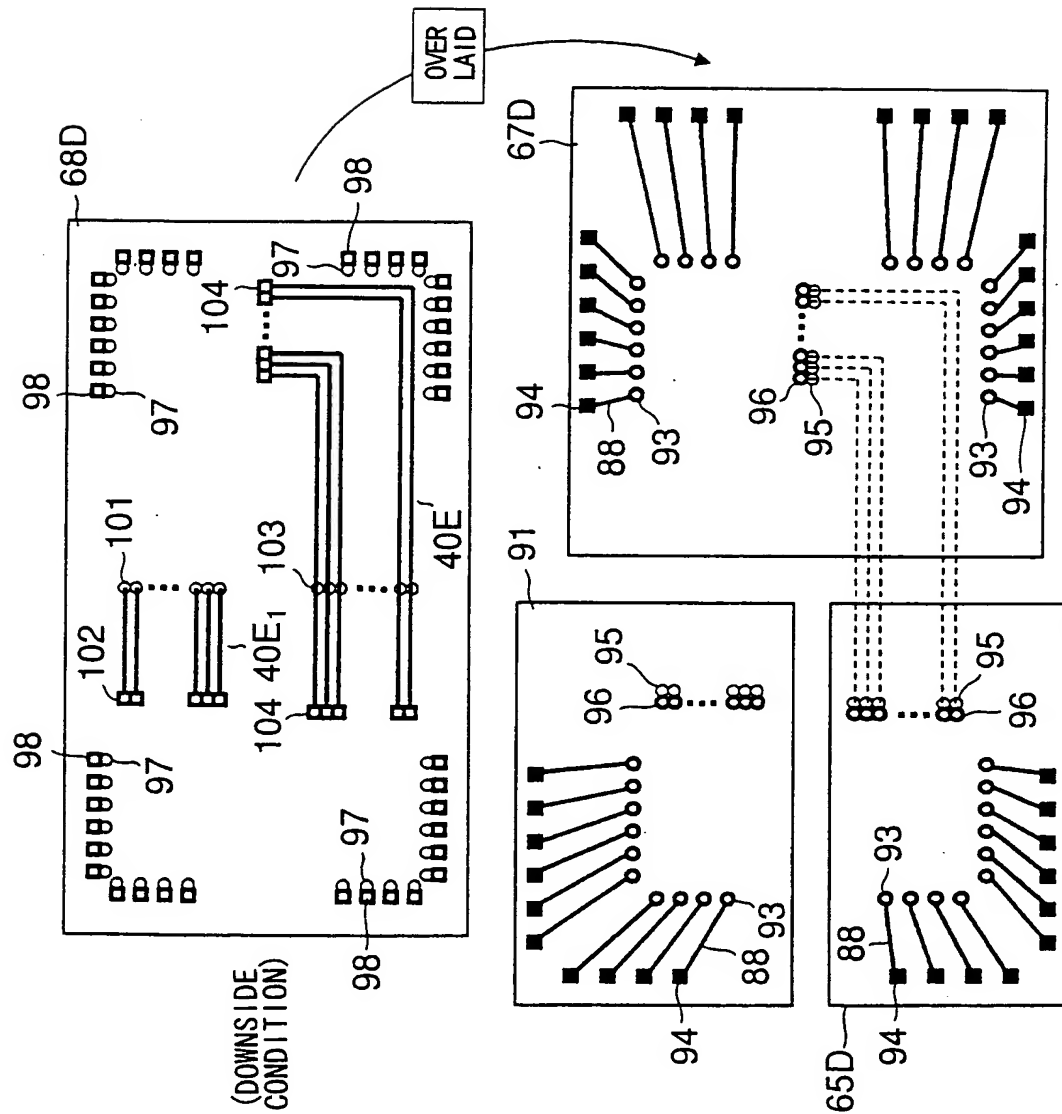


FIG.37

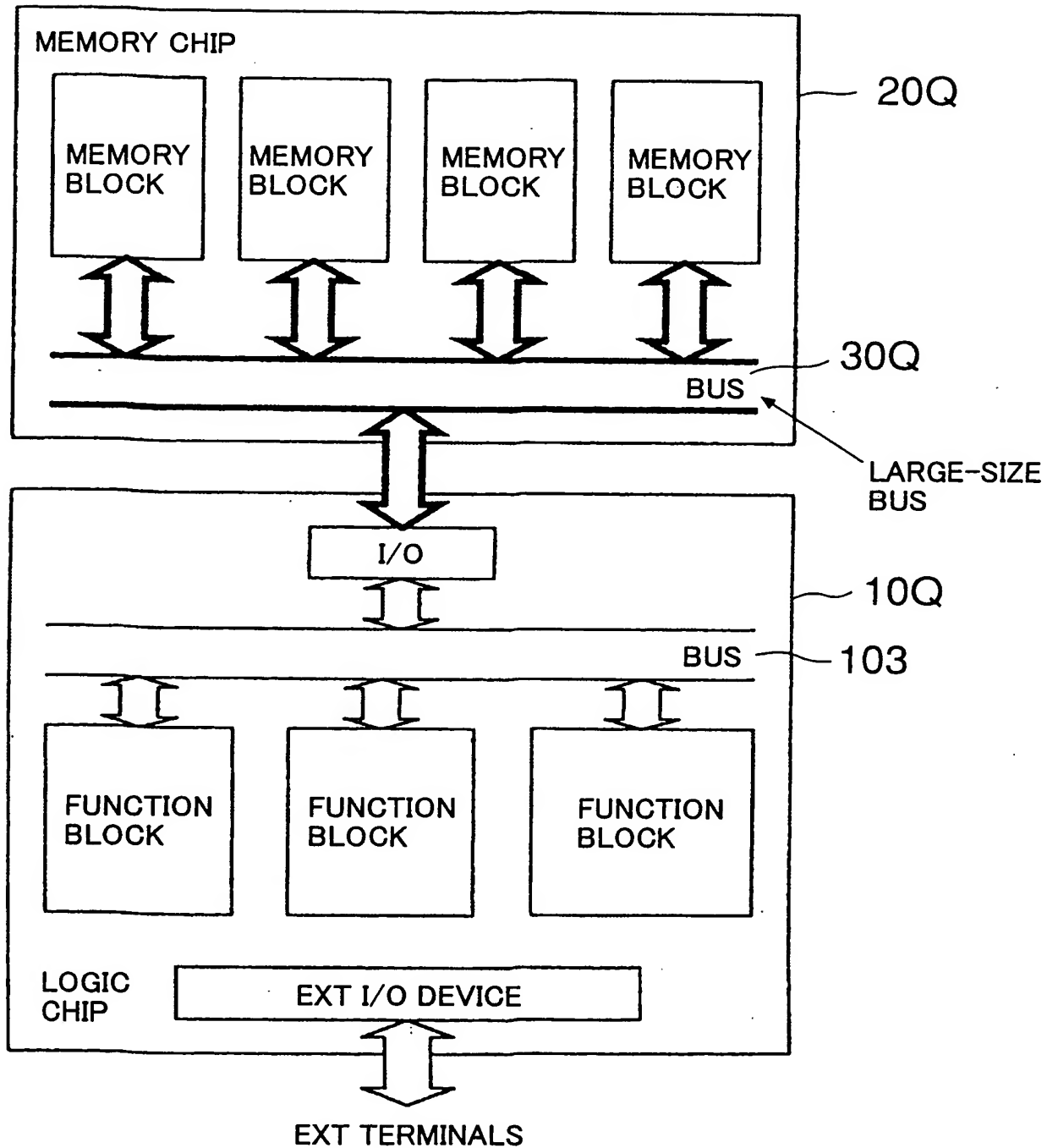


FIG.38

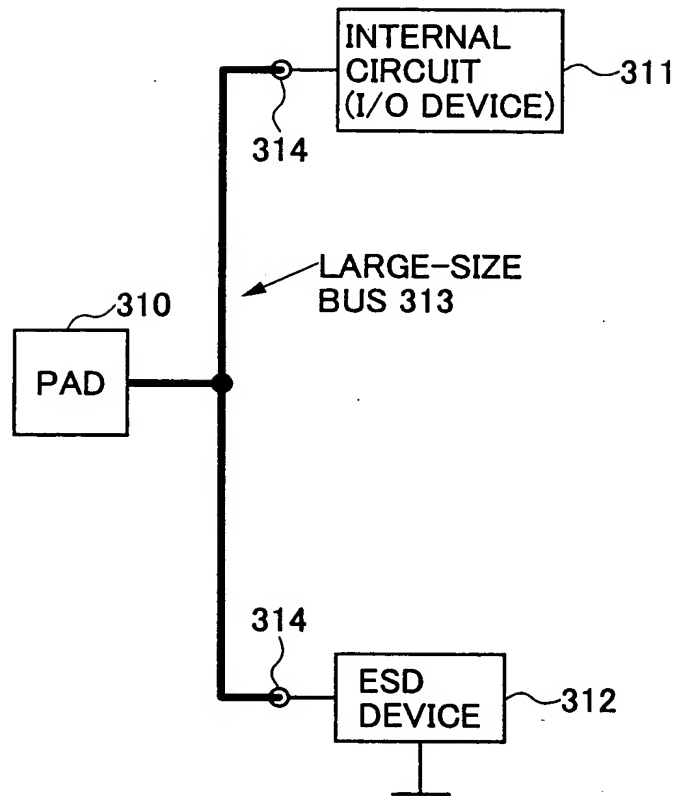


FIG. 39

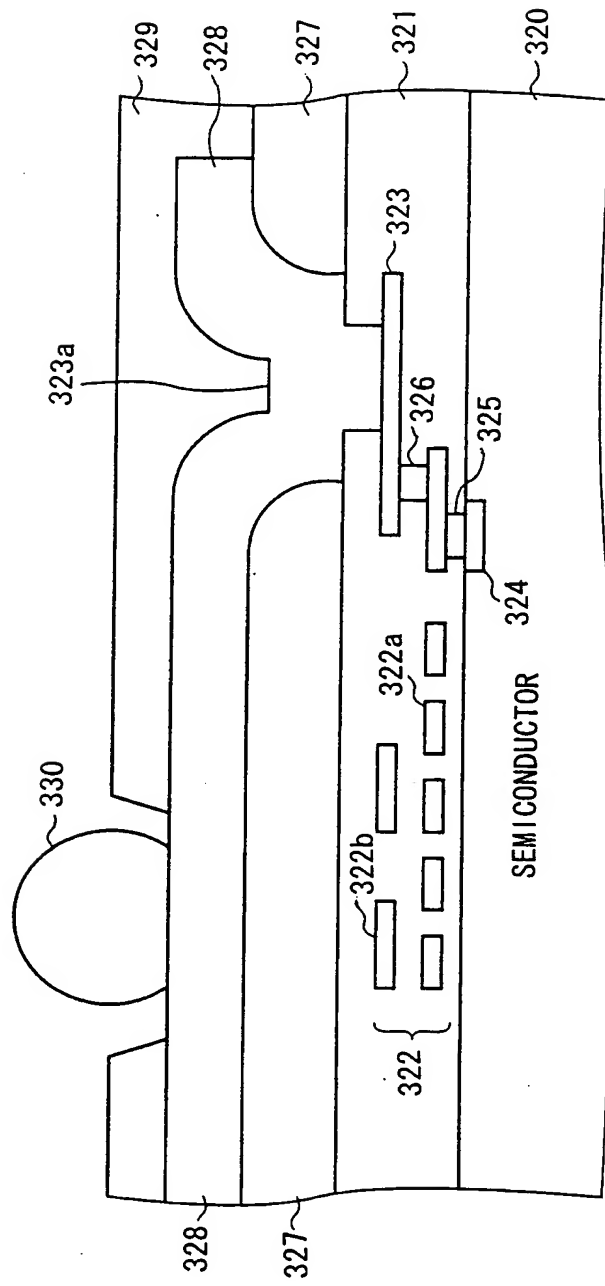




FIG.40

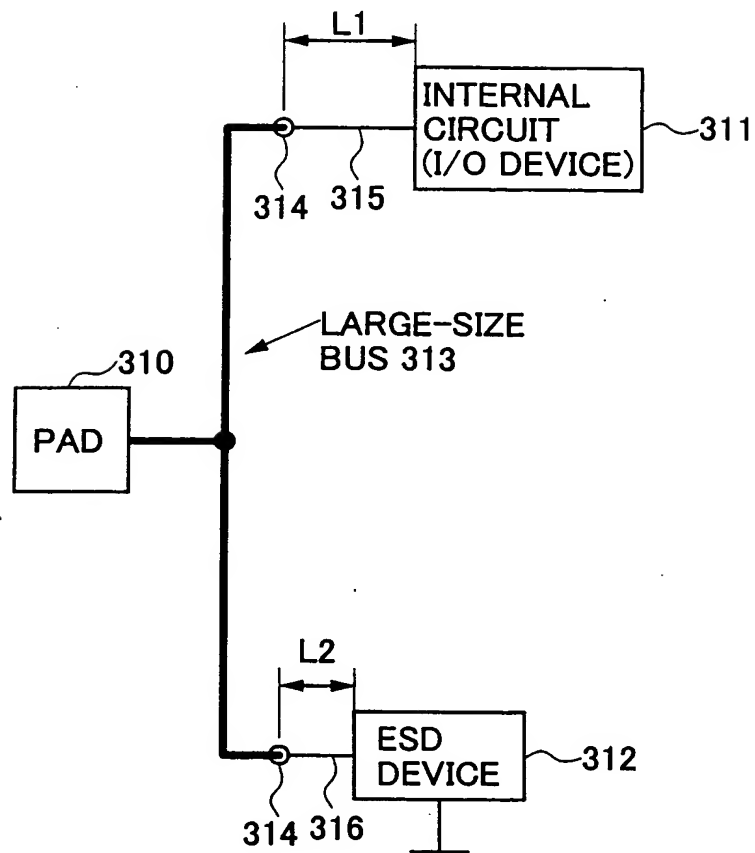


FIG.41

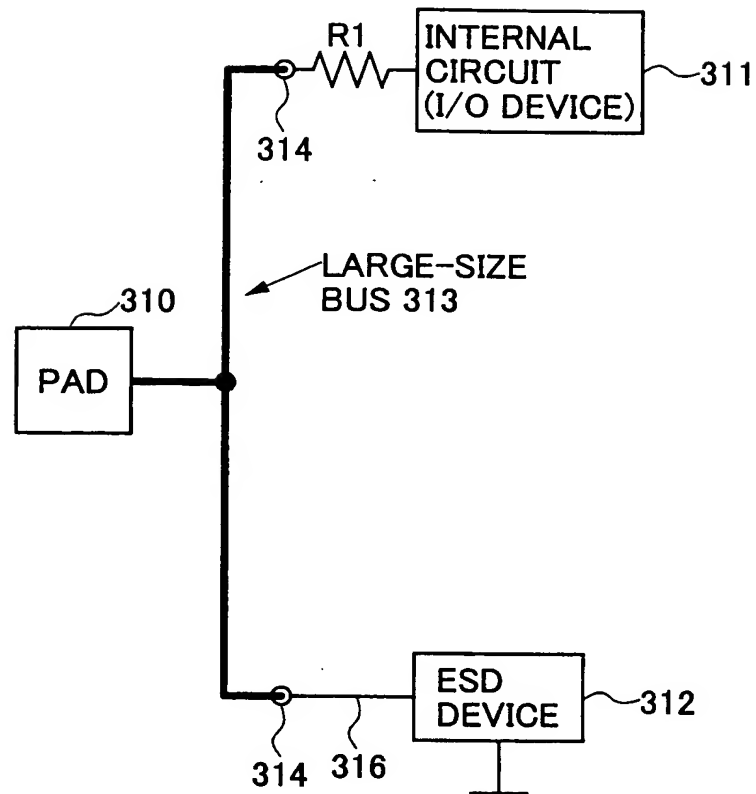


FIG.42

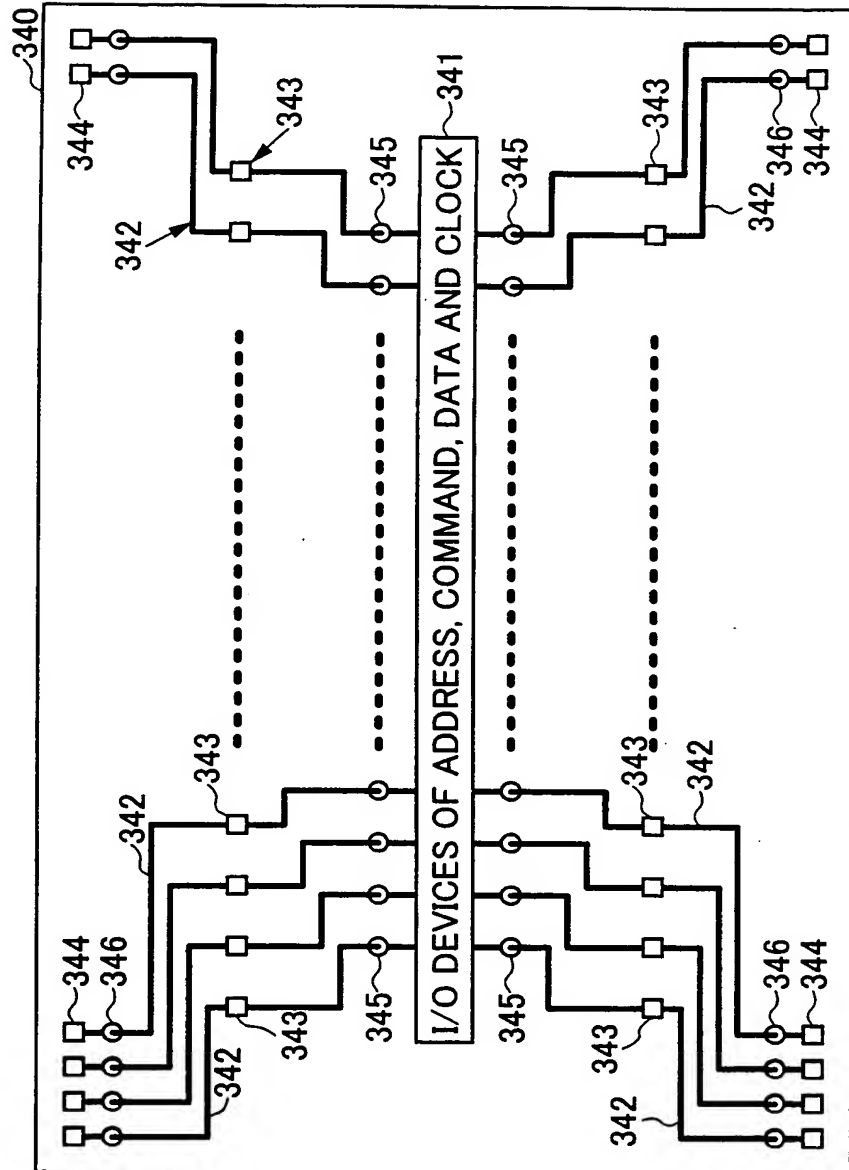


FIG.43

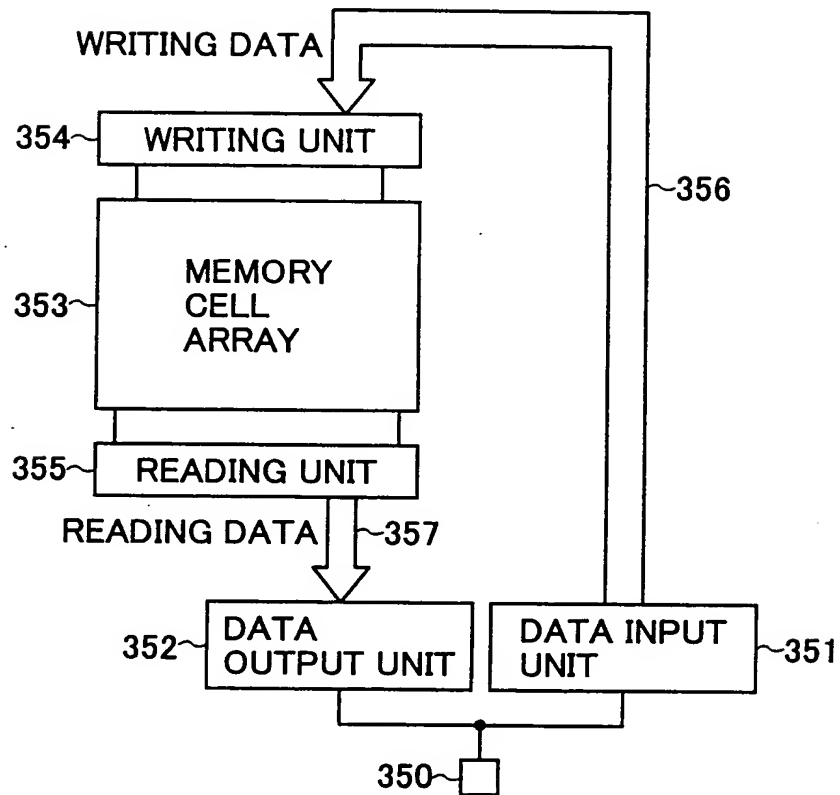


FIG.44A

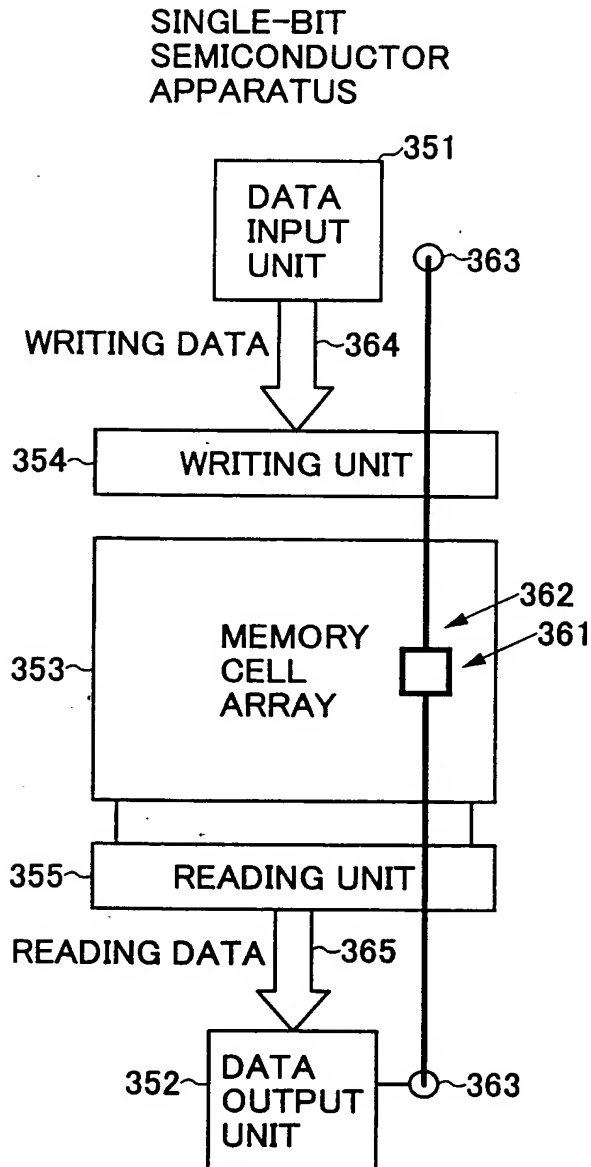


FIG.44B

